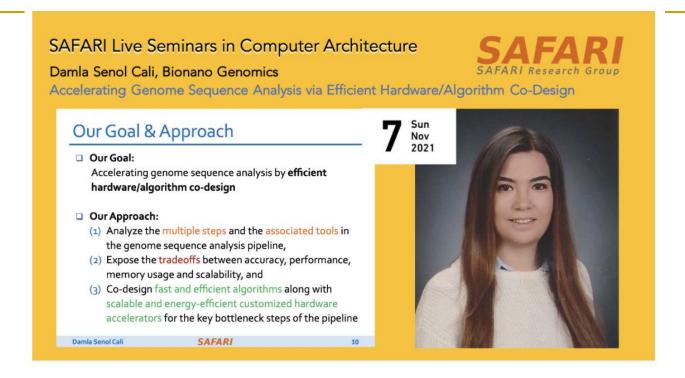
Computer Architecture

Lecture 12a: Low-Latency Memory II

Prof. Onur Mutlu
ETH Zürich
Fall 2021
5 November 2021

SAFARI Live Seminar Nov 7



Sunday, November 07 at 6:00 pm Zurich time (CET)

<u>Damla Senol Cali</u>, <u>Bionano Genomics</u>

<u>Accelerating Genome Sequence Analysis via Efficient Hardware/Algorithm Co-</u> Design

Livestream on YouTube Link

Abstract & Speaker Bio



SAFARI Live Seminar Nov 8



Monday, November 08 at 4:00 pm Zurich time (CET)

Gennady Pekhimenko, University of Toronto, EcoSystem group

Machine Learning Tools in Action

Livestream on YouTube Link

Abstract & Speaker Bio

SAFARI Live Seminar Nov 11



Thursday, November 11 at 11:00 am Zurich time (CET)

<u>Serghei Mangul</u>, University of Southern California, <u>Mangul Lab</u> <u>Opportunities and challenges of computational data-driven immunology</u>

Livestream on YouTube Link

Note: this talk will take place in person at ETH Zentrum. Room info will be posted soon!

Abstract & Speaker Bio

SAFARI Live Seminars



Four Key Current Directions

Fundamentally Secure/Reliable/Safe Architectures

- Fundamentally Energy-Efficient Architectures
 - Memory-centric (Data-centric) Architectures

Fundamentally Low-Latency and Predictable Architectures

Architectures for AI/ML, Genomics, Medicine, Health, ...

Why the Long Memory Latency?

- Reason 1: Design of DRAM Micro-architecture
 - Goal: Maximize capacity/area, not minimize latency
- Reason 2: "One size fits all" approach to latency specification
 - Same latency parameters for all temperatures
 - Same latency parameters for all DRAM chips
 - Same latency parameters for all parts of a DRAM chip
 - Same latency parameters for all supply voltage levels
 - Same latency parameters for all application data
 - **...**

More on AL-DRAM

 Donghyuk Lee, Yoongu Kim, Gennady Pekhimenko, Samira Khan, Vivek Seshadri, Kevin Chang, and Onur Mutlu,
 "Adaptive-Latency DRAM: Optimizing DRAM Timing for the Common-Case"

Proceedings of the <u>21st International Symposium on High-Performance Computer Architecture</u> (**HPCA**), Bay Area, CA, February 2015.

[Slides (pptx) (pdf)] [Full data sets]

Adaptive-Latency DRAM: Optimizing DRAM Timing for the Common-Case

Donghyuk Lee Yoongu Kim Gennady Pekhimenko Samira Khan Vivek Seshadri Kevin Chang Onur Mutlu Carnegie Mellon University

Different Types of Latency Variation

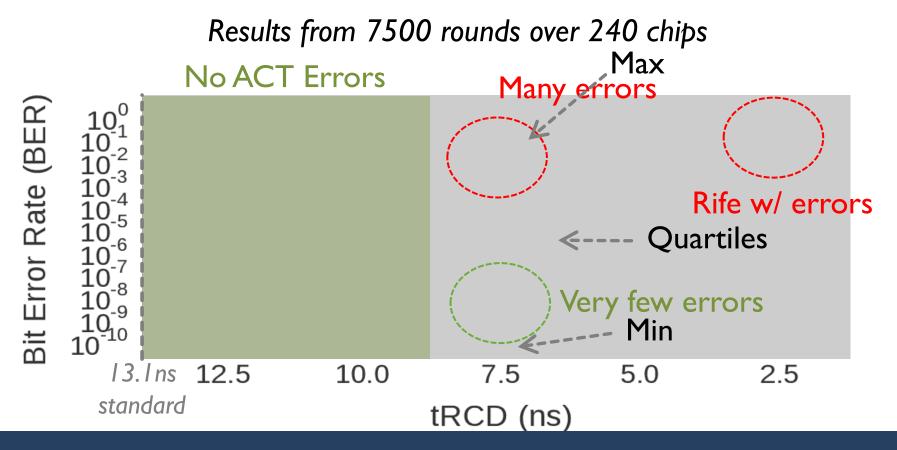
- AL-DRAM exploits latency variation
 - Across time (different temperatures)
 - Across chips

- Is there also latency variation within a chip?
 - Across different parts of a chip

Why the Long Memory Latency?

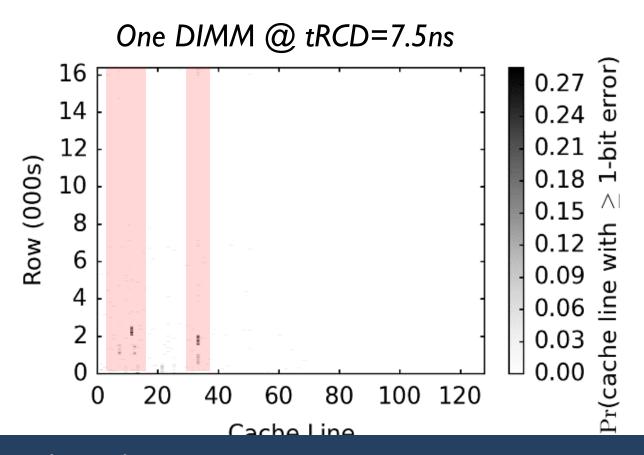
- Reason 1: Design of DRAM Micro-architecture
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 - Same latency parameters for all supply voltage levels
 - Same latency parameters for all application data
 - **...**

Variation in Activation Errors



Modern DRAM chips exhibit significant variation in activation latency

Spatial Locality of Activation Errors

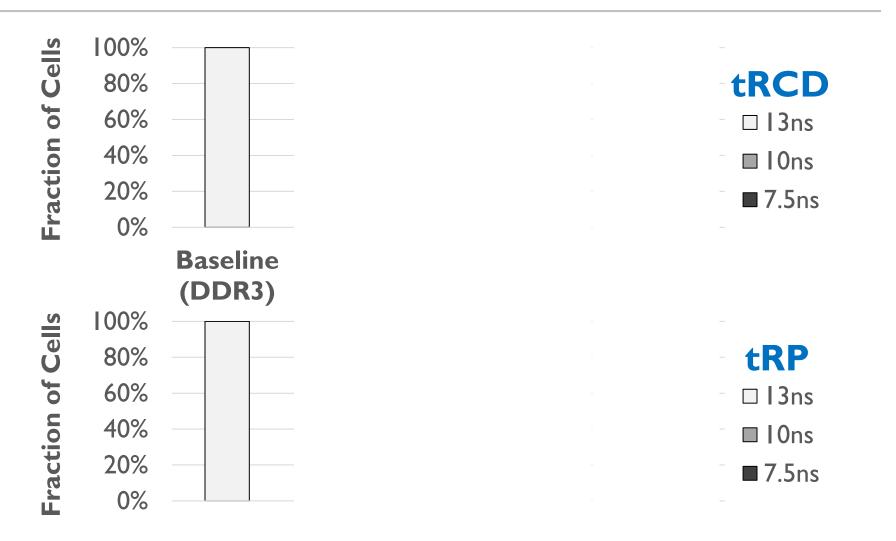


Activation errors are concentrated at certain columns of cells

Mechanism to Reduce DRAM Latency

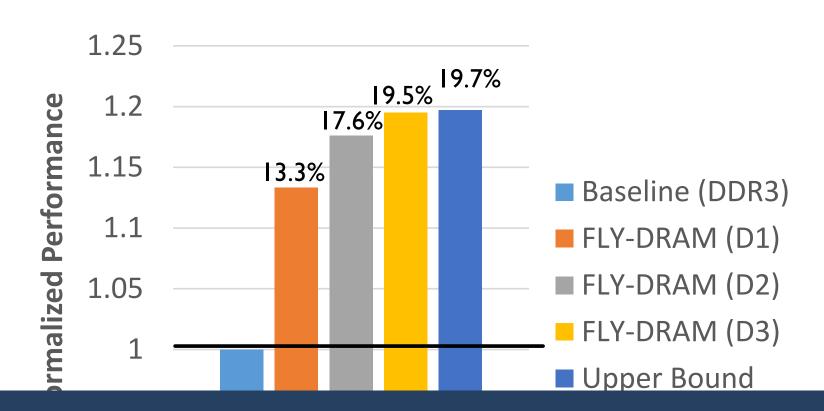
- Observation: DRAM timing errors (slow DRAM cells) are concentrated in certain DRAM regions
- Flexible-LatencY (FLY) DRAM
 - A software-transparent design that reduces latency
- Key idea:
 - 1) Divide memory into regions of different latencies
 - 2) Memory controller: Use lower latency for regions without slow cells; higher latency for other regions

FLY-DRAM Configurations



Chang+, "<u>Understanding Latency Variation in Modern DRAM Chips: Experimental</u>
<u>Characterization, Analysis, and Optimization"</u>," SIGMETRICS 2016.

Results



FLY-DRAM improves performance by exploiting spatial latency variation in DRAM

Chang+, "<u>Understanding Latency Variation in Modern DRAM Chips: Experimental</u>
Characterization, Analysis, and Optimization"," SIGMETRICS 2016.

FLY-DRAM: Advantages & Disadvantages

Advantages

- + Reduces latency significantly
 - + Exploits significant within-chip latency variation

Disadvantages

- Need to determine reliable operating latencies for different parts of a chip → higher testing cost
 - More complicated controller

Analysis of Latency Variation in DRAM Chips

 Kevin Chang, Abhijith Kashyap, Hasan Hassan, Samira Khan, Kevin Hsieh, Donghyuk Lee, Saugata Ghose, Gennady Pekhimenko, Tianshi Li, and Onur Mutlu,

"Understanding Latency Variation in Modern DRAM Chips: Experimental Characterization, Analysis, and Optimization"

Proceedings of the <u>ACM International Conference on Measurement and Modeling of Computer Systems</u> (**SIGMETRICS**), Antibes Juan-Les-Pins, France, June 2016.

[Slides (pptx) (pdf)]

Source Code

Understanding Latency Variation in Modern DRAM Chips: Experimental Characterization, Analysis, and Optimization

Kevin K. Chang¹ Abhijith Kashyap¹ Hasan Hassan^{1,2} Saugata Ghose¹ Kevin Hsieh¹ Donghyuk Lee¹ Tianshi Li^{1,3} Gennady Pekhimenko¹ Samira Khan⁴ Onur Mutlu^{5,1}

¹Carnegie Mellon University ²TOBB ETÜ ³Peking University ⁴University of Virginia ⁵ETH Zürich

Putting It All Together: Solar-DRAM

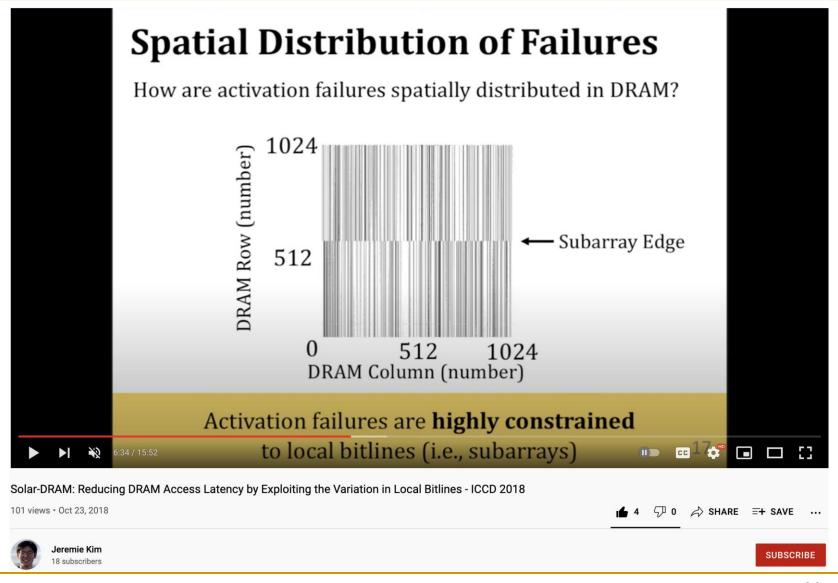
Solar-DRAM: Putting It Together

Jeremie S. Kim, Minesh Patel, Hasan Hassan, and Onur Mutlu,
 "Solar-DRAM: Reducing DRAM Access Latency by
 Exploiting the Variation in Local Bitlines"
 Proceedings of the 36th IEEE International Conference on
 Computer Design (ICCD), Orlando, FL, USA, October 2018.
 [Slides (pptx) (pdf)]
 [Talk Video (16 minutes)]

Solar-DRAM: Reducing DRAM Access Latency by Exploiting the Variation in Local Bitlines

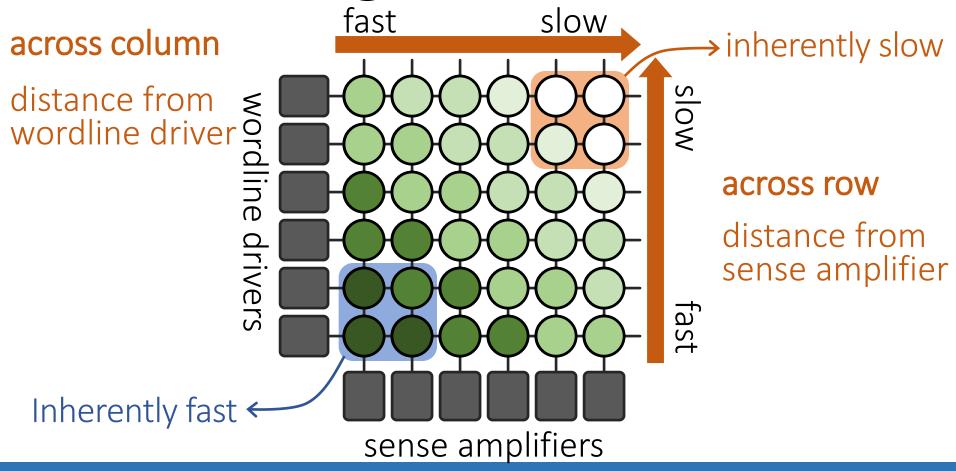
Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§‡}
[‡]Carnegie Mellon University [§]ETH Zürich

More on Solar DRAM



Why Is There Spatial Latency Variation Within a Chip?

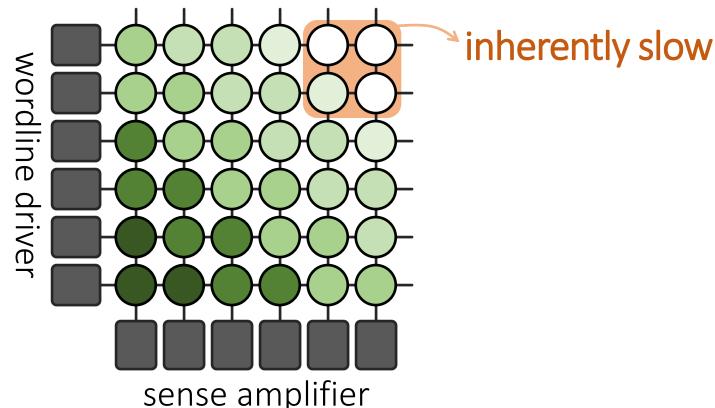
What Is Design-Induced Variation?



Systematic variation in cell access times caused by the **physical organization** of DRAM

DIVA Online **Profiling**

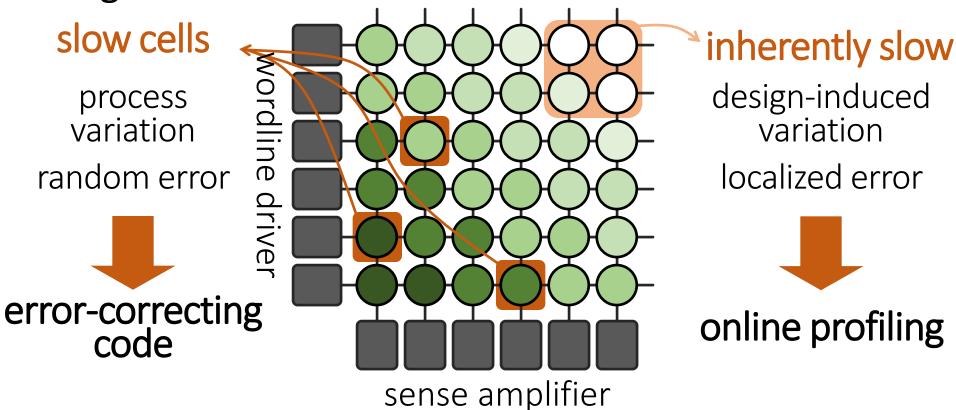
Design-Induced-Variation-Aware



Profile *only slow regions* to determine min. latency Dynamic & low cost latency optimization

DIVA Online **Profiling**

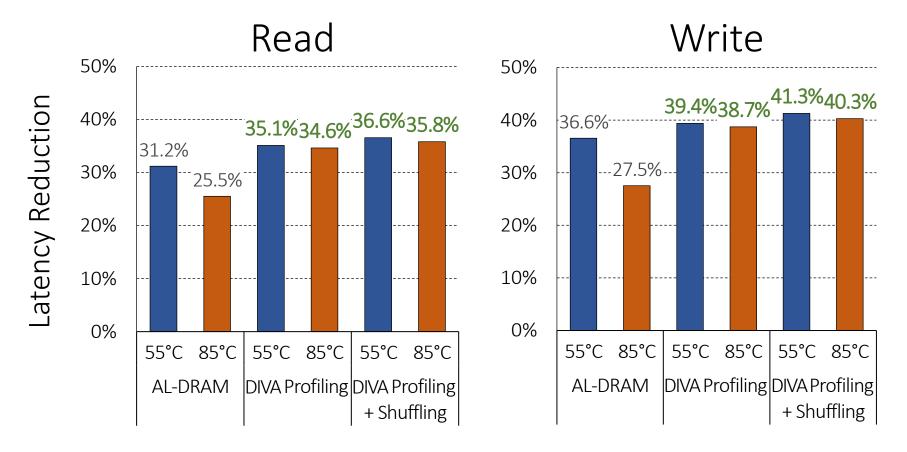
Design-Induced-Variation-Aware



Combine error-correcting codes & online profiling

Reliably reduce DRAM latency

DIVA-DRAM Reduces Latency



DIVA-DRAM *reduces latency more aggressively* and uses ECC to correct random slow cells



DIVA-DRAM: Advantages & Disadvantages

Advantages

- ++ Automatically finds the lowest reliable operating latency at system runtime (lower production-time testing cost)
 - + Reduces latency more than prior methods (w/ ECC)
 - + Reduces latency at high temperatures as well

Disadvantages

- Requires knowledge of inherently-slow regions
- Requires ECC (Error Correcting Codes)
- Imposes overhead during runtime profiling
- More complicated memory controller (capable of profiling)

Design-Induced Latency Variation in DRAM

 Donghyuk Lee, Samira Khan, Lavanya Subramanian, Saugata Ghose, Rachata Ausavarungnirun, Gennady Pekhimenko, Vivek Seshadri, and Onur Mutlu,

"Design-Induced Latency Variation in Modern DRAM Chips:
Characterization, Analysis, and Latency Reduction Mechanisms"
Proceedings of the ACM International Conference on Measurement and
Modeling of Computer Systems (SIGMETRICS), Urbana-Champaign, IL,
USA, June 2017.

Design-Induced Latency Variation in Modern DRAM Chips: Characterization, Analysis, and Latency Reduction Mechanisms

Donghyuk Lee, NVIDIA and Carnegie Mellon University
Samira Khan, University of Virginia
Lavanya Subramanian, Saugata Ghose, Rachata Ausavarungnirun, Carnegie Mellon University
Gennady Pekhimenko, Vivek Seshadri, Microsoft Research
Onur Mutlu, ETH Zürich and Carnegie Mellon University

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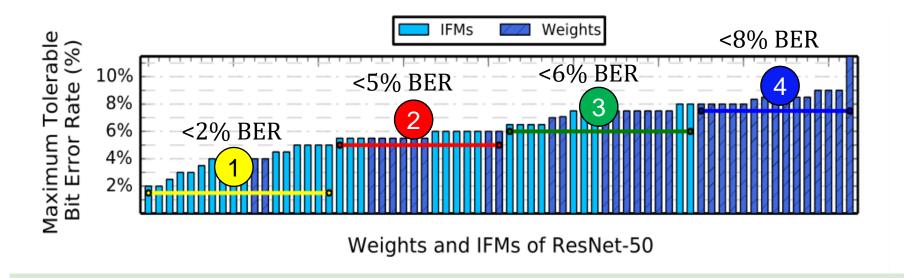
Data-Aware DRAM Latency for DNN Inference

- Deep Neural Network evaluation is very DRAM-intensive (especially for large networks)
- 1. Some data and layers in DNNs are very tolerant to errors
- 2. Reduce DRAM latency and voltage on such data and layers
- 3. While still achieving a user-specified DNN accuracy target by making training DRAM-error-aware

Data-aware management of DRAM latency and voltage for Deep Neural Network Inference

Example DNN Data Type to DRAM Mapping

Mapping example of ResNet-50:



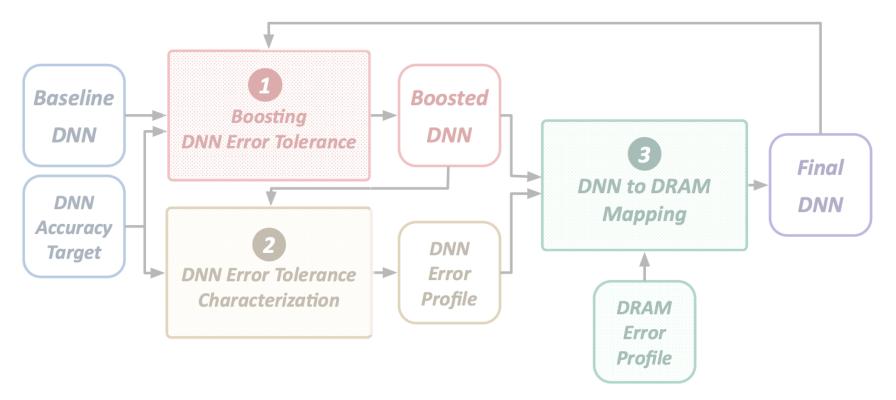
Map more error-tolerant DNN layers to DRAM partitions with lower voltage/latency

4 DRAM partitions with different error rates

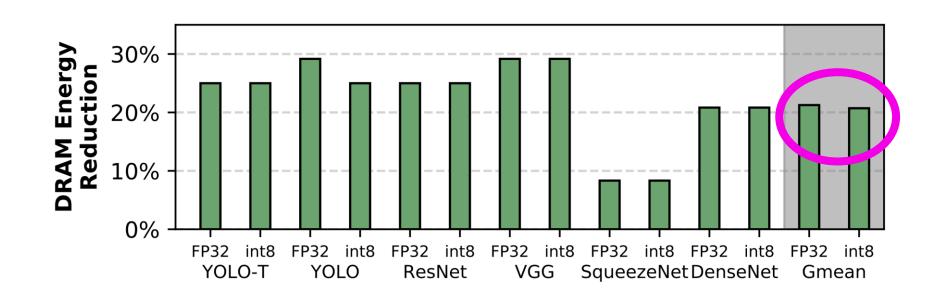
EDEN: Overview

Key idea: Enable accurate, efficient DNN inference using approximate DRAM

EDEN is an **iterative** process that has **3 key steps**

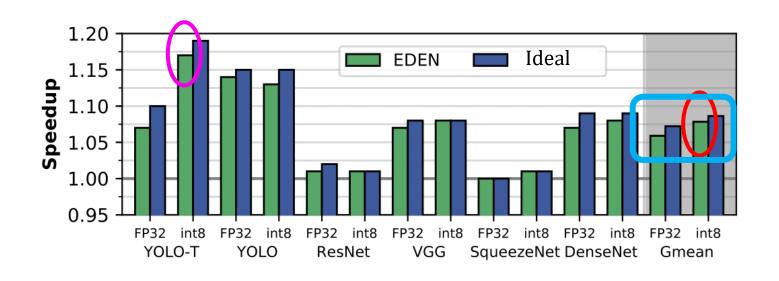


CPU: DRAM Energy Evaluation



Average 21% DRAM energy reduction maintaining accuracy within 1% of original

CPU: Performance Evaluation



Average 8% system speedup
Some workloads achieve 17% speedup

EDEN achieves **close to the ideal** speedup possible via tRCD scaling

GPU, Eyeriss, and TPU: Energy Evaluation

• GPU: average 37% energy reduction

Eyeriss: average 31% energy reduction

TPU: average 32% energy reduction

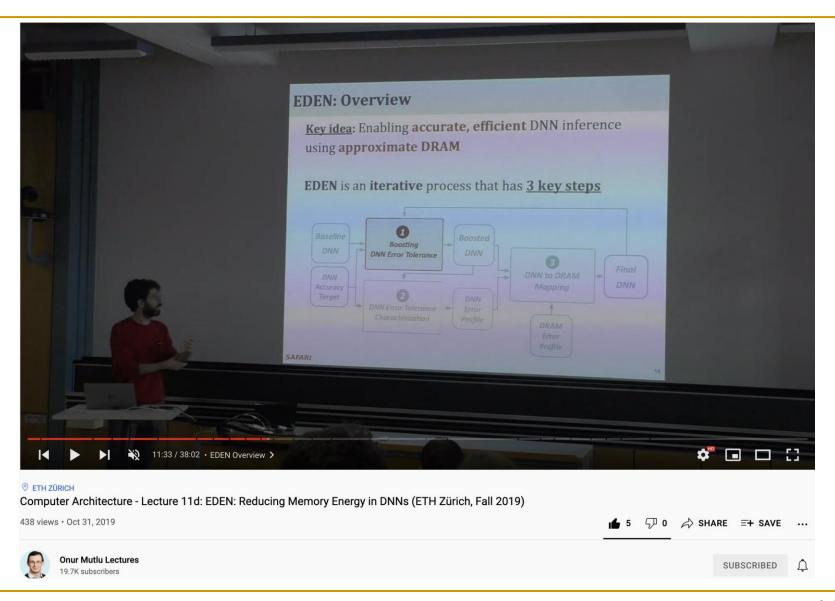
EDEN: Data-Aware Efficient DNN Inference

Skanda Koppula, Lois Orosa, A. Giray Yaglikci, Roknoddin Azizi, Taha Shahroodi, Konstantinos Kanellopoulos, and Onur Mutlu,
 "EDEN: Enabling Energy-Efficient, High-Performance Deep
 Neural Network Inference Using Approximate DRAM"
 Proceedings of the 52nd International Symposium on
 Microarchitecture (MICRO), Columbus, OH, USA, October 2019.
 [Lightning Talk Slides (pptx) (pdf)]
 [Lightning Talk Video (90 seconds)]

EDEN: Enabling Energy-Efficient, High-Performance Deep Neural Network Inference Using Approximate DRAM

Skanda Koppula Lois Orosa A. Giray Yağlıkçı Roknoddin Azizi Taha Shahroodi Konstantinos Kanellopoulos Onur Mutlu ETH Zürich

More on EDEN



Recall: Exploiting Memory Error Tolerance with Hybrid Memory Systems

Vulnerable data

Tolerant data

Reliable memory

Low-cost memory

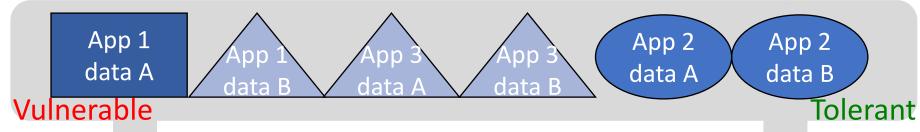
On Microsoft's Web Search workload Reduces server hardware cost by 4.7 % Achieves single server availability target of 99.90 %

Heterogeneous-Reliability Memory [DSN 2014]

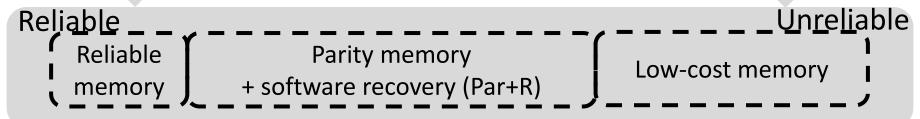
Recall: Heterogeneous-Reliability Memory



Step 1: Characterize and classify application memory error tolerance



Step 2: Map application data to the HRM system enabled by SW/HW cooperative solutions



More on Heterogeneous-Reliability Memory

Yixin Luo, Sriram Govindan, Bikash Sharma, Mark Santaniello, Justin Meza, Aman Kansal, Jie Liu, Badriddine Khessib, Kushagra Vaid, and Onur Mutlu, "Characterizing Application Memory Error Vulnerability to Optimize Data Center Cost via Heterogeneous-Reliability Memory"
Proceedings of the 44th Annual IEEE/IFIP International Conference on Dependable Systems and Networks (DSN), Atlanta, GA, June 2014. [Summary]
[Slides (pptx) (pdf)] [Coverage on ZDNet]

Characterizing Application Memory Error Vulnerability to Optimize Datacenter Cost via Heterogeneous-Reliability Memory

Yixin Luo Sriram Govindan* Bikash Sharma* Mark Santaniello* Justin Meza Aman Kansal* Jie Liu* Badriddine Khessib* Kushagra Vaid* Onur Mutlu Carnegie Mellon University, yixinluo@cs.cmu.edu, {meza, onur}@cmu.edu
*Microsoft Corporation, {srgovin, bsharma, marksan, kansal, jie.liu, bkhessib, kvaid}@microsoft.com

Why the Long Memory Latency?

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 - Same latency parameters for all supply voltage levels
 - Same latency parameters for all application data
 - **...**

Understanding & Exploiting the Voltage-Latency-Reliability Relationship

Analysis of Latency-Voltage in DRAM Chips

 Kevin Chang, A. Giray Yaglikci, Saugata Ghose, Aditya Agrawal, Niladrish Chatterjee, Abhijith Kashyap, Donghyuk Lee, Mike O'Connor, Hasan Hassan, and Onur Mutlu,

"Understanding Reduced-Voltage Operation in Modern DRAM Devices: Experimental Characterization, Analysis, and Mechanisms"

Proceedings of the <u>ACM International Conference on Measurement and</u> <u>Modeling of Computer Systems</u> (**SIGMETRICS**), Urbana-Champaign, IL, USA, June 2017.

Understanding Reduced-Voltage Operation in Modern DRAM Chips: Characterization, Analysis, and Mechanisms

Kevin K. Chang[†] Abdullah Giray Yağlıkçı[†] Saugata Ghose[†] Aditya Agrawal[¶] Niladrish Chatterjee[¶] Abhijith Kashyap[†] Donghyuk Lee[¶] Mike O'Connor^{¶,‡} Hasan Hassan[§] Onur Mutlu^{§,†}

[†]Carnegie Mellon University [¶]NVIDIA [‡]The University of Texas at Austin [§]ETH Zürich

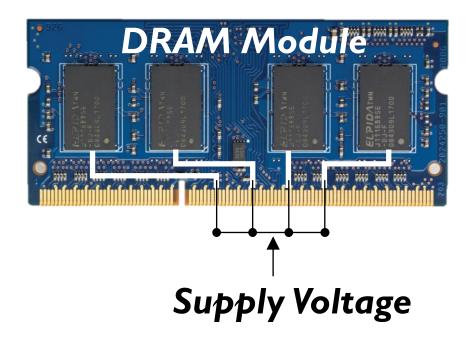
Key Questions

 How does reducing voltage affect reliability (errors)?

 How does reducing voltage affect DRAM latency?

 How do we design a new DRAM energy reduction mechanism?

Supply Voltage Control on DRAM



Adjust the supply voltage to every chip on the same module

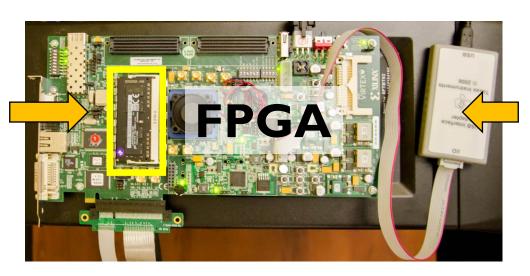
Custom Testing Platform

SoftMC [Hassan+, HPCA'17]: FPGA testing platform to

- I) Adjust supply voltage to DRAM modules
- 2) Schedule DRAM commands to DRAM modules

Existing systems: DRAM commands not exposed to users

DRAM module



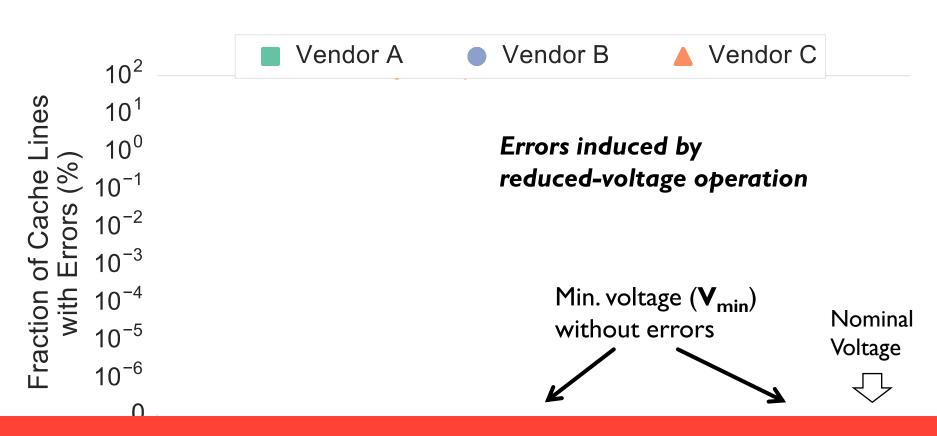
Voltage controller

https://github.com/CMU-SAFARI/DRAM-Voltage-Study

Tested DRAM Modules

- I24 DDR3L (low-voltage) DRAM chips
 - 31 SO-DIMMs
 - I.35V (DDR3 uses I.5V)
 - Density: 4Gb per chip
 - Three major vendors/manufacturers
 - Manufacturing dates: 2014-2016
- Iteratively read every bit in each 4Gb chip under a wide range of supply voltage levels: I.35V to I.0V (-26%)

Reliability Worsens with Lower Voltage

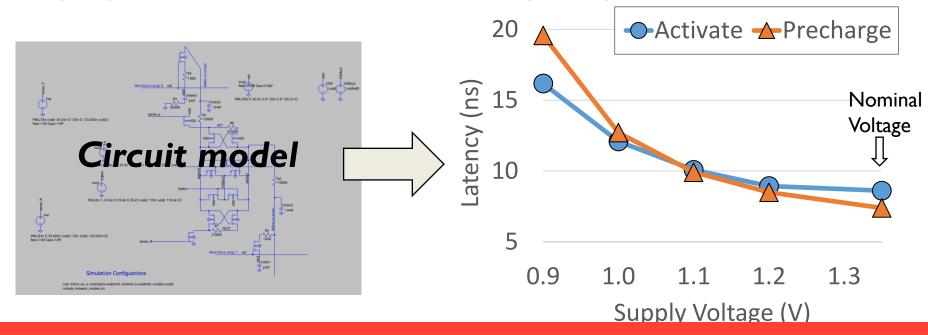


Reducing voltage below V_{min} causes an increasing number of errors

Source of Errors

Detailed circuit simulations (SPICE) of a DRAM cell array to model the behavior of DRAM operations

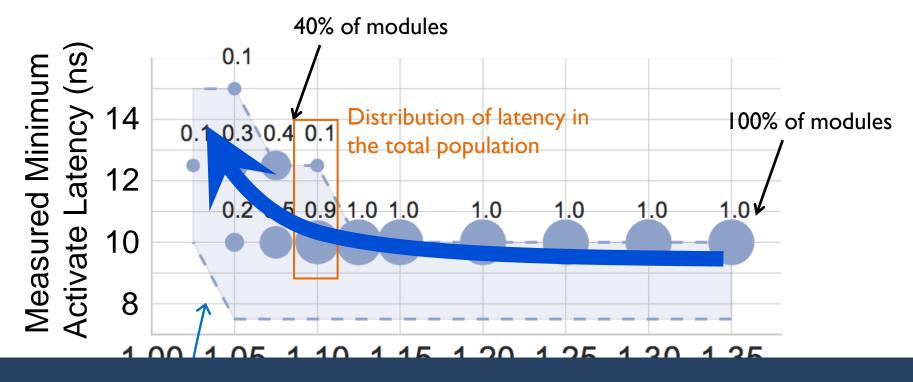
https://github.com/CMU-SAFARI/DRAM-Voltage-Study



Reliable low-voltage operation requires higher latency

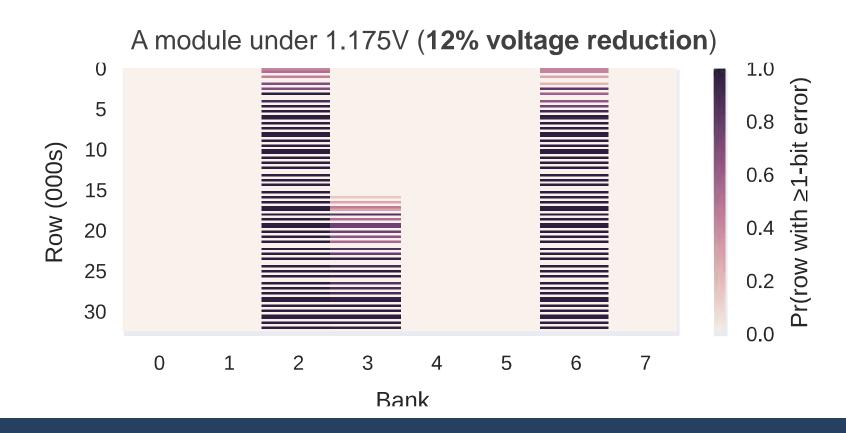
DIMMs Operating at Higher Latency

Measured minimum latency that does not cause errors in DRAM modules



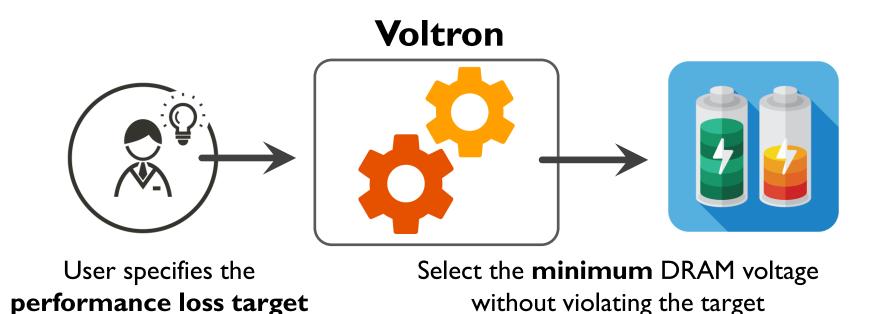
DRAM requires longer latency to access data without errors at lower voltage

Spatial Locality of Errors



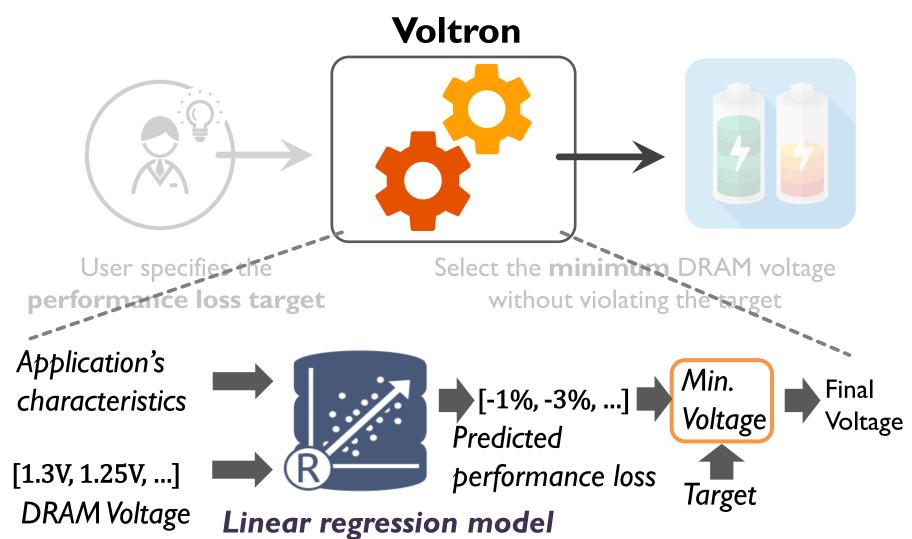
Errors concentrate in certain regions

Voltron Overview

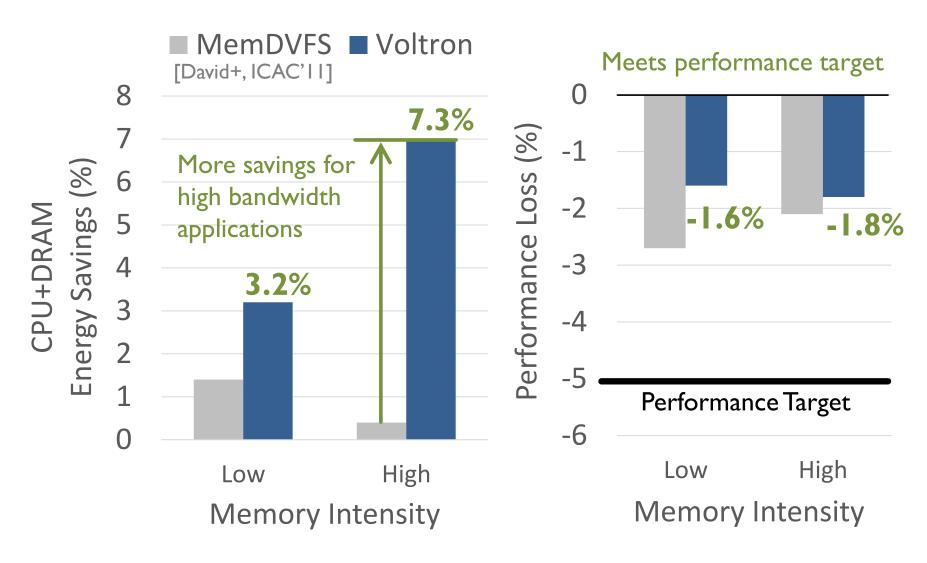


How do we predict performance loss due to increased latency under low DRAM voltage?

Linear Model to Predict Performance



Energy Savings with Bounded Performance





Voltron: Advantages & Disadvantages

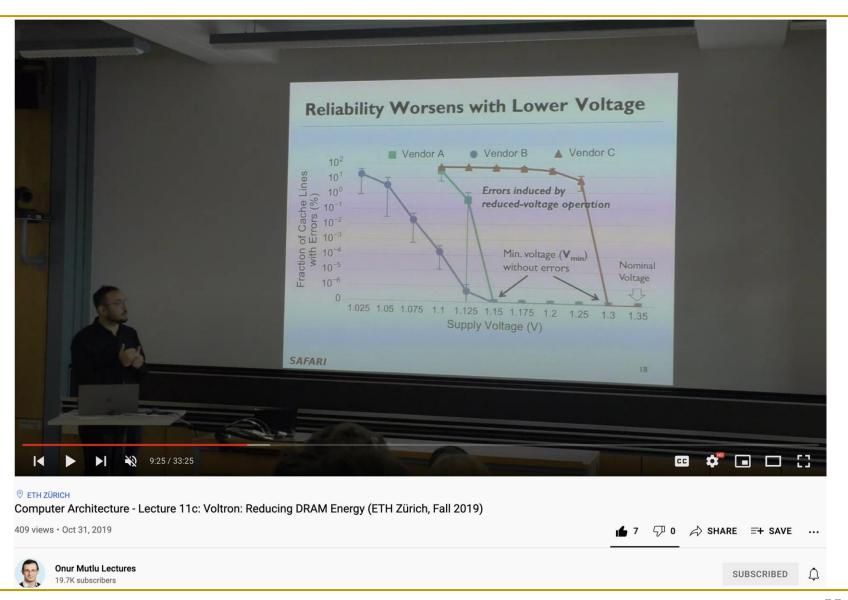
Advantages

- + Can trade-off between voltage and latency to improve energy or performance
 - + Can exploit the high voltage margin present in DRAM

Disadvantages

- Requires finding the reliable operating voltage for each chip → higher testing cost
 - More complicated memory controller

More on Voltron



Reducing Memory Latency to Support Security Primitives

Using Memory for Security

- Generating True Random Numbers (using DRAM)
 - Kim et al., HPCA 2019
 - Olgun et al., ISCA 2021

- Evaluating Physically Unclonable Functions (using DRAM)
 - □ Kim et al., HPCA 2018

- Quickly Destroying In-Memory Data (using DRAM)
 - Orosa et al., arxiv 2019 + ISCA 2021

DRAM Latency PUFs

Jeremie S. Kim, Minesh Patel, Hasan Hassan, and Onur Mutlu,
 "The DRAM Latency PUF: Quickly Evaluating Physical Unclonable
 Functions by Exploiting the Latency-Reliability Tradeoff in Modern DRAM Devices"

Proceedings of the <u>24th International Symposium on High-Performance Computer</u> <u>Architecture</u> (**HPCA**), Vienna, Austria, February 2018.

[Lightning Talk Video]

[Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)]

[Full Talk Lecture Video (28 minutes)]

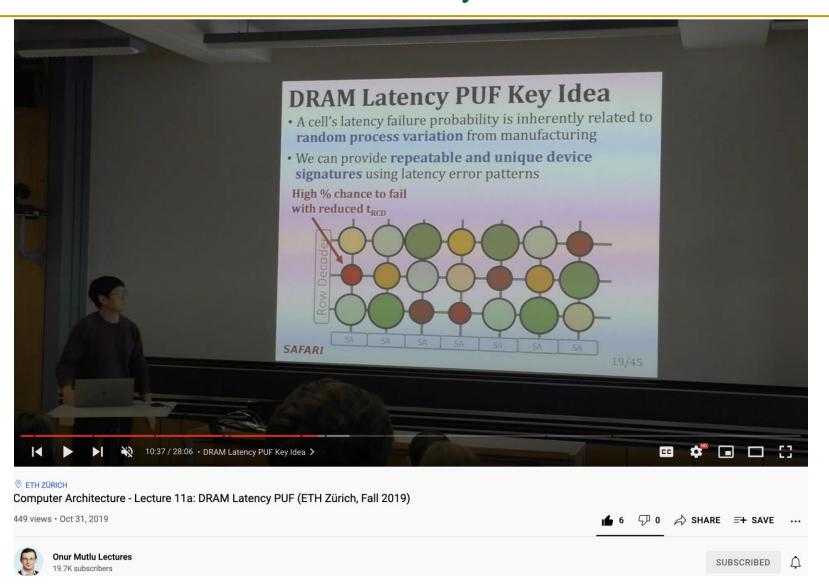
The DRAM Latency PUF:

Quickly Evaluating Physical Unclonable Functions by Exploiting the Latency-Reliability Tradeoff in Modern Commodity DRAM Devices

Jeremie S. Kim^{†§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§†}

[†]Carnegie Mellon University [§]ETH Zürich

More on DRAM Latency PUFs



DRAM Latency True Random Number Generator

Jeremie S. Kim, Minesh Patel, Hasan Hassan, Lois Orosa, and Onur Mutlu,
 "D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput"

Proceedings of the <u>25th International Symposium on High-Performance Computer</u> <u>Architecture</u> (**HPCA**), Washington, DC, USA, February 2019.

[Slides (pptx) (pdf)]

[Full Talk Video (21 minutes)]

[Full Talk Lecture Video (27 minutes)]

Top Picks Honorable Mention by IEEE Micro.

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Lois Orosa[§] Onur Mutlu^{§‡} [‡]Carnegie Mellon University [§]ETH Zürich

60

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

<u>Jeremie S. Kim</u> Minesh Patel Hasan Hassan Lois Orosa Onur Mutlu

SAFARI

HPCA 2019



Carnegie Mellon

D-RaNGe Executive Summary

- Motivation: High-throughput true random numbers enable system security and various randomized algorithms.
 - Many systems (e.g., IoT, mobile, embedded) do not have dedicated True
 Random Number Generator (TRNG) hardware but have DRAM devices
- **Problem**: Current DRAM-based TRNGs either
 - 1. do **not** sample a fundamentally non-deterministic entropy source
 - 2. are **too slow** for continuous high-throughput operation
- <u>Goal</u>: A novel and effective TRNG that uses <u>existing</u> commodity DRAM to provide random values with 1) <u>high-throughput</u>, 2) <u>low latency</u> and 3) no adverse effect on concurrently running applications
- <u>D-RaNGe:</u> Reduce DRAM access latency **below reliable values** and exploit DRAM cells' failure probabilities to generate random values
- Evaluation:
 - 1. Experimentally characterize 282 real LPDDR4 DRAM devices
 - 2. **D-RaNGe** (717.4 Mb/s) has significantly higher throughput (211x)
 - 3. **D-RaNGe (100ns)** has significantly lower latency (180x)

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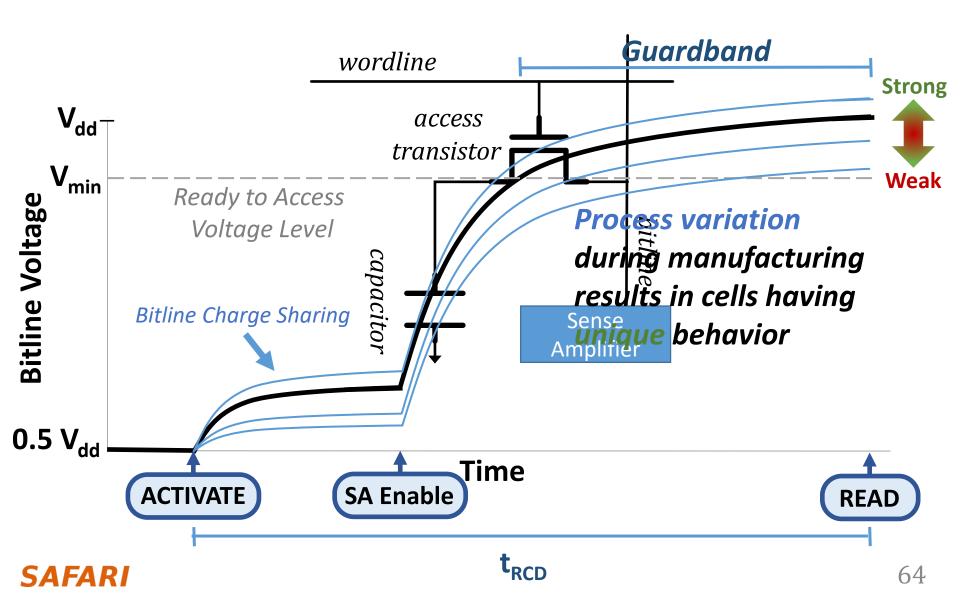
DRAM Latency Characterization of 282 LPDDR4 DRAM Devices

 Latency failures come from accessing DRAM with reduced timing parameters.

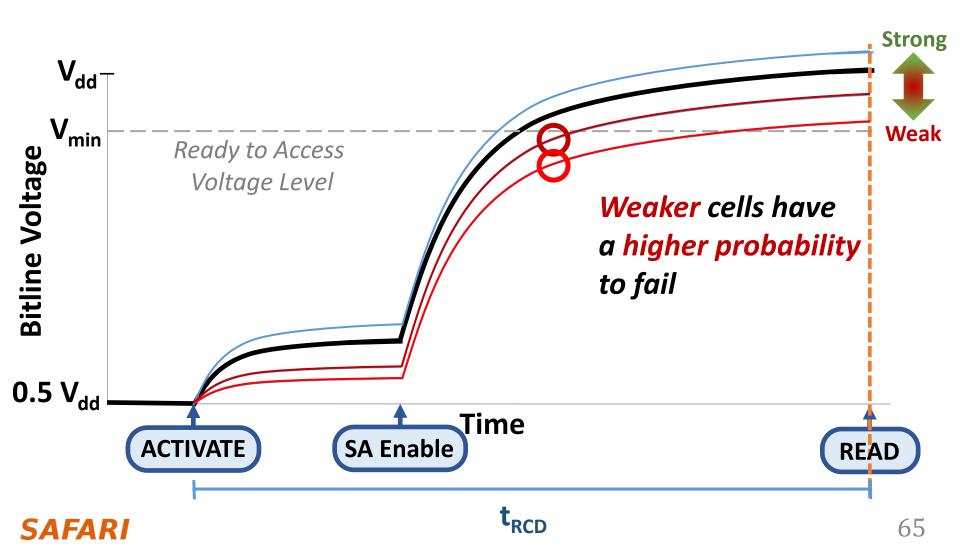
Key Observations:

- 1. A cell's **latency failure** probability is determined by **random process variation**
- 2. Some cells fail randomly

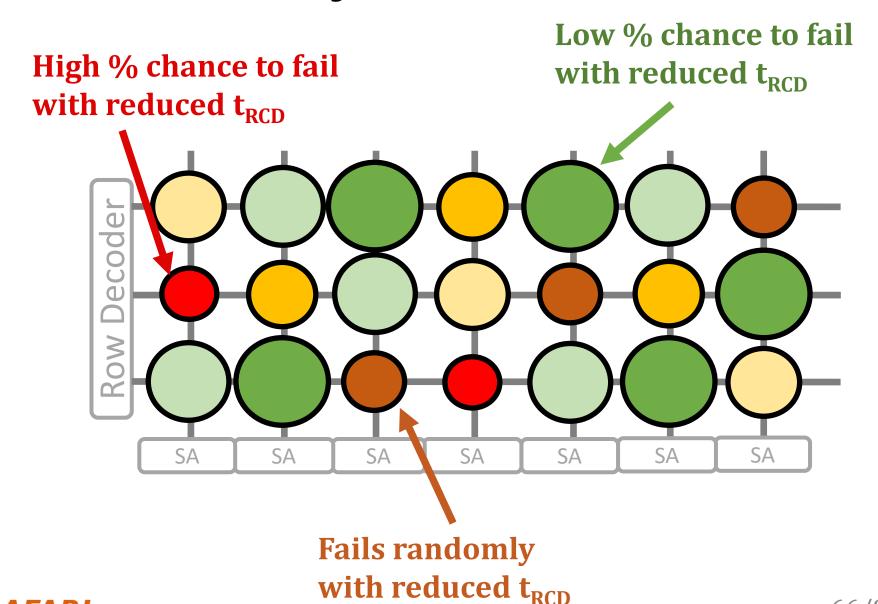
DRAM Accesses and Failures



DRAM Accesses and Failures



D-RaNGe Key Idea



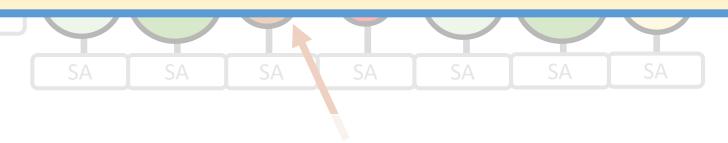
SAFARI

D-RaNGe Key Idea

High % chance to fail with reduced t_{RCD}

Low % chance to fail with reduced t_{RCD}

We refer to cells that fail randomly when accessed with a reduced t_{RCD} as RNG cells



Fails randomly with reduced t_{RCD}

Our D-RaNGe Evaluation

- We generate random values by repeatedly accessing RNG cells and aggregating the data read
- The random data satisfies the NIST statistical test suite for randomness
- The D-RaNGE generates random numbers
 - **Throughput**: 717.4 Mb/s
 - **Latency**: 64 bits in <1us
 - Power: 4.4 nJ/bit

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

<u>Jeremie S. Kim</u> Minesh Patel Hasan Hassan Lois Orosa Onur Mutlu

SAFARI

HPCA 2019



Carnegie Mellon

More on D-RaNGe

Jeremie S. Kim, Minesh Patel, Hasan Hassan, Lois Orosa, and Onur Mutlu,
 "D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput"

Proceedings of the <u>25th International Symposium on High-Performance Computer</u> <u>Architecture</u> (**HPCA**), Washington, DC, USA, February 2019.

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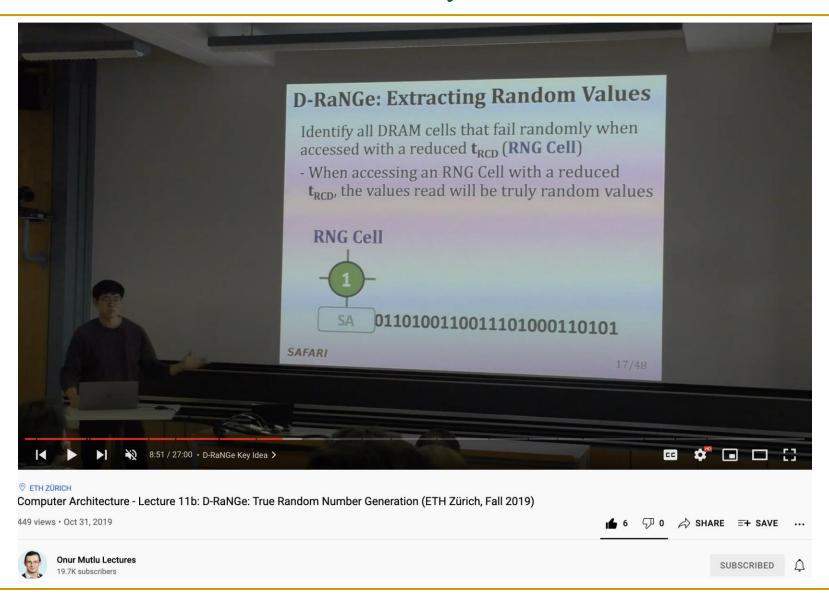
Top Picks Honorable Mention by IEEE Micro.

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Lois Orosa[§] Onur Mutlu^{§‡} [‡]Carnegie Mellon University [§]ETH Zürich

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More on DRAM Latency TRNGs



In-DRAM True Random Number Generation

 Ataberk Olgun, Minesh Patel, A. Giray Yaglikci, Haocong Luo, Jeremie S. Kim, F. Nisa Bostanci, Nandita Vijaykumar, Oguz Ergin, and Onur Mutlu,

"QUAC-TRNG: High-Throughput True Random Number Generation Using Quadruple Row Activation in Commodity DRAM Chips"

Proceedings of the <u>48th International Symposium on Computer Architecture</u> (**ISCA**), Virtual, June 2021.

[Slides (pptx) (pdf)]

[Short Talk Slides (pptx) (pdf)]

[Talk Video (25 minutes)]

[SAFARI Live Seminar Video (1 hr 26 mins)]

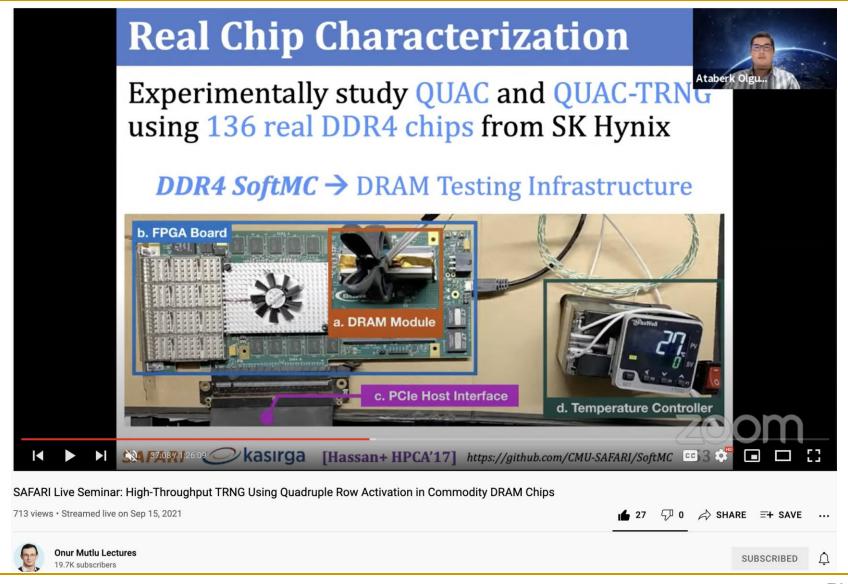
QUAC-TRNG: High-Throughput True Random Number Generation Using Quadruple Row Activation in Commodity DRAM Chips

Ataberk Olgun^{§†} Minesh Patel[§] A. Giray Yağlıkçı[§] Haocong Luo[§] Jeremie S. Kim[§] F. Nisa Bostancı^{§†} Nandita Vijaykumar^{§⊙} Oğuz Ergin[†] Onur Mutlu[§]

§ETH Zürich † TOBB University of Economics and Technology $^{\odot}$ University of Toronto

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More on QUAC-TRNG



Reducing Refresh Latency

Reducing Refresh Latency

Anup Das, Hasan Hassan, and Onur Mutlu,
 "VRL-DRAM: Improving DRAM Performance via
 Variable Refresh Latency"
 Proceedings of the <u>55th Design Automation</u>
 Conference (DAC), San Francisco, CA, USA, June 2018.

VRL-DRAM: Improving DRAM Performance via Variable Refresh Latency

Anup Das
Drexel University
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ETH Zürich
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Reducing Memory Latency by Exploiting Memory Access Patterns

ChargeCache: Exploiting Access Patterns

 Hasan Hassan, Gennady Pekhimenko, Nandita Vijaykumar, Vivek Seshadri, Donghyuk Lee, Oguz Ergin, and Onur Mutlu,
 "ChargeCache: Reducing DRAM Latency by Exploiting Row Access Locality"

Proceedings of the <u>22nd International Symposium on High-</u> <u>Performance Computer Architecture</u> (**HPCA**), Barcelona, Spain, March 2016.

[Slides (pptx) (pdf)]
[Source Code]

ChargeCache: Reducing DRAM Latency by Exploiting Row Access Locality

Hasan Hassan^{†*}, Gennady Pekhimenko[†], Nandita Vijaykumar[†] Vivek Seshadri[†], Donghyuk Lee[†], Oguz Ergin^{*}, Onur Mutlu[†]

ChargeCache: Executive Summary

• <u>Goal</u>: Reduce average DRAM access latency with no modification to the existing DRAM chips

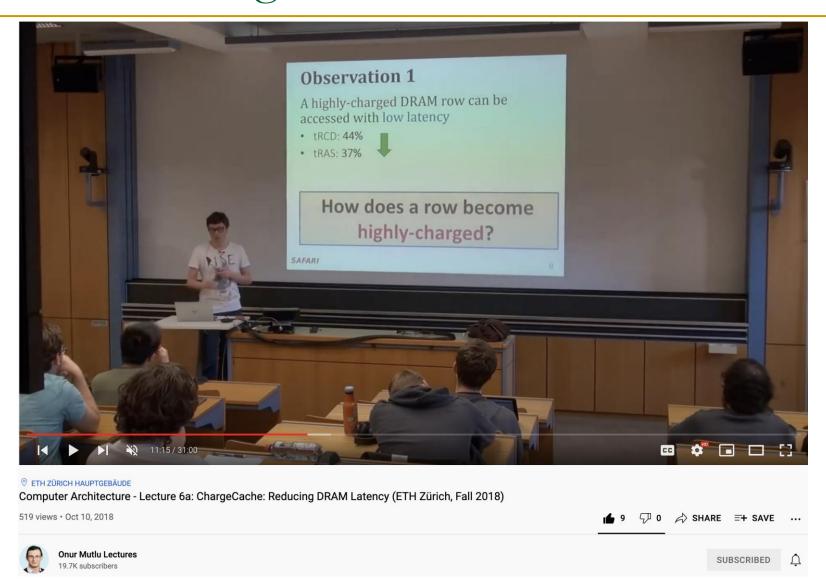
• Observations:

- 1) A highly-charged DRAM row can be accessed with low latency
- 2) A row's charge is restored when the row is accessed
- 3) A recently-accessed row is likely to be accessed again: Row Level Temporal Locality (RLTL)
- <u>Key Idea</u>: Track recently-accessed DRAM rows and use lower timing parameters if such rows are accessed again

ChargeCache:

- Low cost & no modifications to the DRAM
- Higher performance (8.6-10.6% on average for 8-core)
- Lower DRAM energy (7.9% on average)

More on ChargeCache



Partial Restoration of Cell Charge

 Yaohua Wang, Arash Tavakkol, Lois Orosa, Saugata Ghose, Nika Mansouri Ghiasi, Minesh Patel, Jeremie S. Kim, Hasan Hassan, Mohammad Sadrosadati, and Onur Mutlu,

"Reducing DRAM Latency via Charge-Level-Aware Look-Ahead Partial Restoration"

Proceedings of the <u>51st International Symposium on</u> <u>Microarchitecture</u> (**MICRO**), Fukuoka, Japan, October 2018.

Reducing DRAM Latency via Charge-Level-Aware Look-Ahead Partial Restoration

```
Yaohua Wang<sup>†§</sup> Arash Tavakkol<sup>†</sup> Lois Orosa<sup>†*</sup> Saugata Ghose<sup>‡</sup> Nika Mansouri Ghiasi<sup>†</sup> Minesh Patel<sup>†</sup> Jeremie S. Kim<sup>‡†</sup> Hasan Hassan<sup>†</sup> Mohammad Sadrosadati<sup>†</sup> Onur Mutlu<sup>†‡</sup> 

†ETH Zürich <sup>§</sup>National University of Defense Technology <sup>‡</sup>Carnegie Mellon University *University of Campinas
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Parallelizing Refreshes and Accesses

 Kevin Chang, Donghyuk Lee, Zeshan Chishti, Alaa Alameldeen, Chris Wilkerson, Yoongu Kim, and Onur Mutlu,
 "Improving DRAM Performance by Parallelizing Refreshes with

"Improving DRAM Performance by Parallelizing Refreshes with Accesses"

Proceedings of the <u>20th International Symposium on High-Performance</u> <u>Computer Architecture</u> (**HPCA**), Orlando, FL, February 2014.

[Summary] [Slides (pptx) (pdf)]

Reducing Performance Impact of DRAM Refresh by Parallelizing Refreshes with Accesses

Kevin Kai-Wei Chang Donghyuk Lee Zeshan Chishti†

Alaa R. Alameldeen† Chris Wilkerson† Yoongu Kim Onur Mutlu

Carnegie Mellon University †Intel Labs

On DRAM Power Consumption

VAMPIRE DRAM Power Model

Saugata Ghose, A. Giray Yaglikci, Raghav Gupta, Donghyuk Lee, Kais Kudrolli, William X. Liu, Hasan Hassan, Kevin K. Chang, Niladrish Chatterjee, Aditya Agrawal, Mike O'Connor, and Onur Mutlu,

"What Your DRAM Power Models Are Not Telling You: Lessons from a Detailed **Experimental Study**"

Proceedings of the <u>ACM International Conference on Measurement and Modeling of</u> Computer Systems (SIGMETRICS), Irvine, CA, USA, June 2018.

[Abstract]

[POMACS Journal Version (same content, different format)]

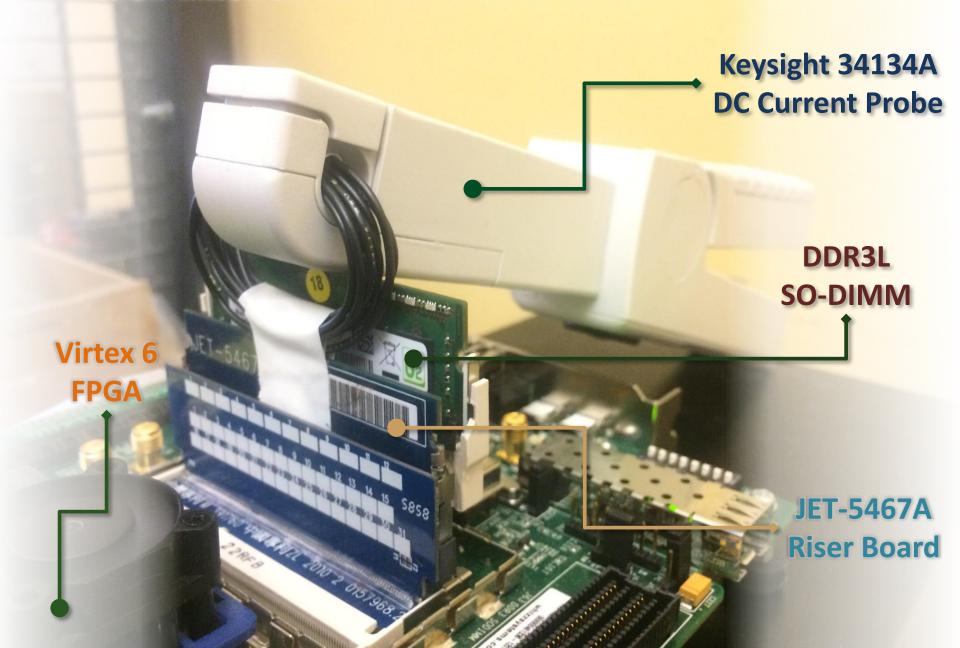
[Slides (pptx) (pdf)]

[VAMPIRE DRAM Power Model]

What Your DRAM Power Models Are Not Telling You: Lessons from a Detailed Experimental Study

Saugata Ghose[†] Abdullah Giray Yağlıkçı^{‡†} Raghav Gupta[†] Donghyuk Lee[§] Kais Kudrolli[†] William X. Liu[†] Hasan Hassan[‡] Kevin K. Chang[†] Mike O'Connor[§]¶ Onur Mutlu^{‡†} Niladrish Chatterjee[§] Aditya Agrawal[§]

Power Measurement Platform



Summary: Low-Latency Memory

Challenge and Opportunity for Future

Fundamentally Low Latency Computing Architectures

Summary: Tackling Long Memory Latency

- Reason 1: Design of DRAM Micro-architecture
 - Goal: Maximize capacity/area, not minimize latency
- Reason 2: "One size fits all" approach to latency specification
 - Same latency parameters for all temperatures
 - Same latency parameters for all DRAM chips (e.g., rows)
 - Same latency parameters for all parts of a DRAM chip
 - Same latency parameters for all supply voltage levels
 - Same latency parameters for all application data
 - **...**

We Can Reduce Memory Latency with Change of Mindset

Main Memory Needs Intelligent Controllers to Reduce Latency

Some Solution Principles

- Data-centric design
- All components intelligent
- Better cross-layer communication, better interfaces
- Better-than-worst-case design
- Heterogeneity
- Flexibility, adaptability

Open minds

Four Key Current Directions

Fundamentally Secure/Reliable/Safe Architectures

- Fundamentally Energy-Efficient Architectures
 - Memory-centric (Data-centric) Architectures

Fundamentally Low-Latency and Predictable Architectures

Architectures for AI/ML, Genomics, Medicine, Health, ...

Computer Architecture

Lecture 12a: Low-Latency Memory II

Prof. Onur Mutlu
ETH Zürich
Fall 2021

5 November 2021

Solar-DRAM

Solar-DRAM: Putting It Together

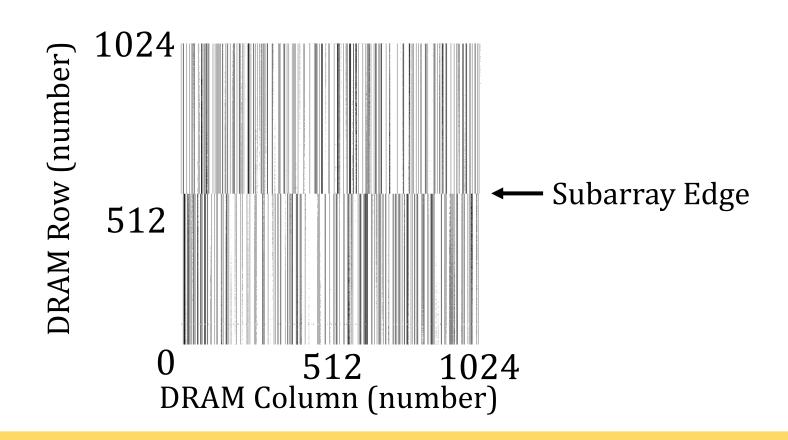
Jeremie S. Kim, Minesh Patel, Hasan Hassan, and Onur Mutlu,
 "Solar-DRAM: Reducing DRAM Access Latency by
 Exploiting the Variation in Local Bitlines"
 Proceedings of the 36th IEEE International Conference on
 Computer Design (ICCD), Orlando, FL, USA, October 2018.
 [Slides (pptx) (pdf)]
 [Talk Video (16 minutes)]

Solar-DRAM: Reducing DRAM Access Latency by Exploiting the Variation in Local Bitlines

Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§‡}
[‡]Carnegie Mellon University [§]ETH Zürich

Spatial Distribution of Failures

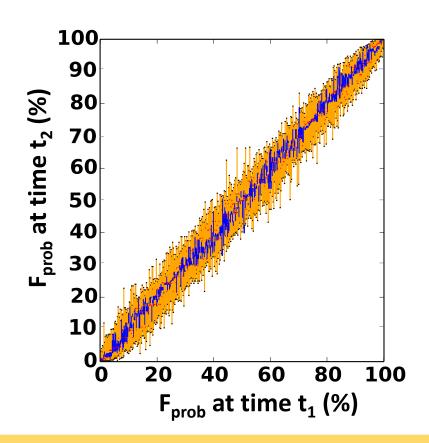
How are activation failures spatially distributed in DRAM?



Activation failures are **highly constrained** to local bitlines

Short-term Variation

Does a bitline's probability of failure change over time?



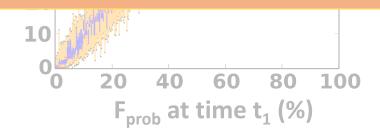
A **weak bitline** is likely to remain **weak** and a **strong bitline** is likely to remain **strong** over time

Short-term Variation

Does a bitline's probability of failure change over time?



We can rely on a **static profile** of weak bitlines to determine whether an access will cause failures

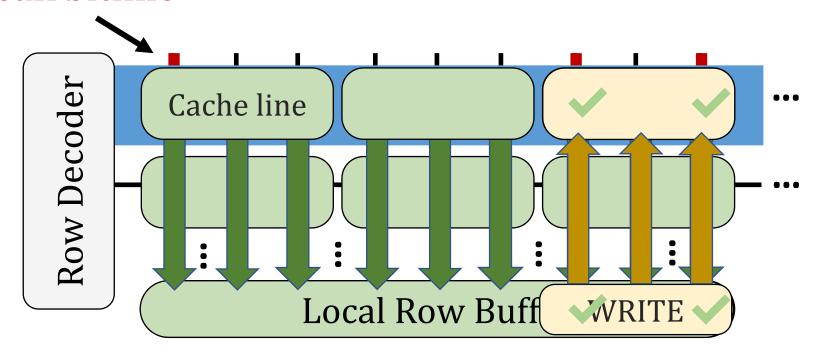


A **weak bitline** is likely to remain **weak** and a **strong bitline** is likely to remain **strong** over time

Write Operations

How are write operations affected by reduced t_{RCD} ?

Weak bitline



We can reliably issue write operations with significantly reduced \mathbf{t}_{RCD} (e.g., by 77%)

Solar-DRAM

Uses a static profile of weak subarray columns

- Identifies subarray columns as weak or strong
- Obtained in a one-time profiling step

Three Components

- 1. Variable-latency cache lines (VLC)
- 2. Reordered subarray columns (RSC)
- 3. Reduced latency for writes (RLW)

Solar-DRAM

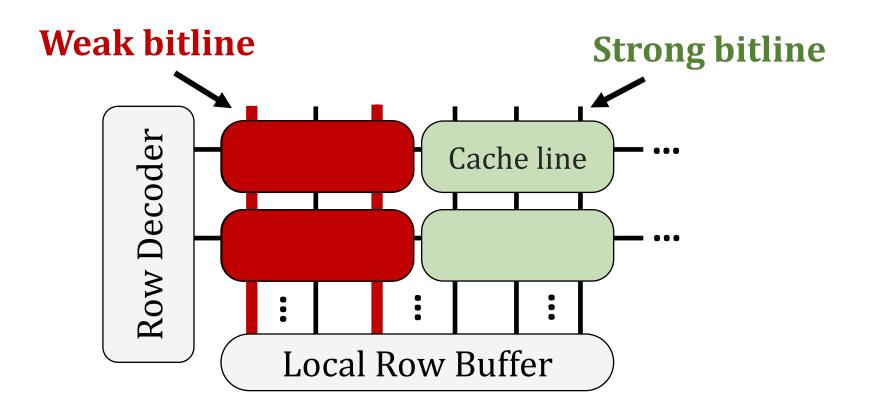
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Solar-DRAM: VLC (I)



Identify cache lines comprised of **strong bitlines**Access such cache lines with a **reduced t**_{RCD}

Solar-DRAM

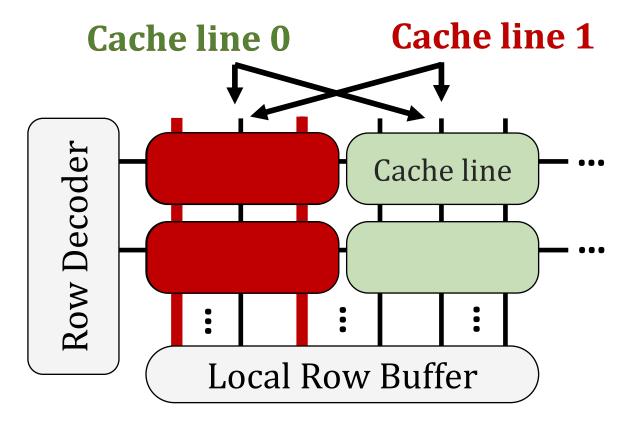
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- Obtained in a one-time profiling step

Three Components

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- 2. Reordered subarray columns (RSC)
- 3. Reduced latency for writes (RLW)

Solar-DRAM: RSC (II)



Remap cache lines across DRAM at the memory controller level so cache line 0 will likely map to a **strong** cache line

Solar-DRAM

Uses a static profile of weak subarray columns

- Identifies subarray columns as weak or strong
- Obtained in a one-time profiling step

Three Components

- 1. Variable-latency cache lines (VLC)
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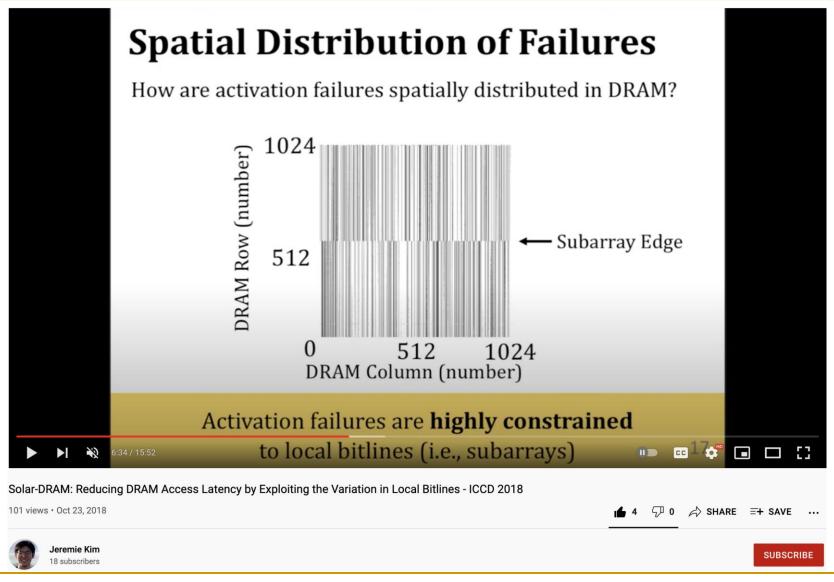
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Solar-DRAM: Reducing DRAM Access Latency by Exploiting the Variation in Local Bitlines

Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§‡}
[‡]Carnegie Mellon University [§]ETH Zürich

More on Solar DRAM



Understanding & Exploiting the Voltage-Latency-Reliability Relationship

Analysis of Latency-Voltage in DRAM Chips

 Kevin Chang, A. Giray Yaglikci, Saugata Ghose, Aditya Agrawal, Niladrish Chatterjee, Abhijith Kashyap, Donghyuk Lee, Mike O'Connor, Hasan Hassan, and <u>u</u>,

"Understanding Reduced-Voltage Operation in Modern DRAM Devices: Experimental Characterization, Analysis, and Mechanisms"

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Understanding Reduced-Voltage Operation in Modern DRAM Chips: Characterization, Analysis, and Mechanisms

Kevin K. Chang[†] Abdullah Giray Yağlıkçı[†] Saugata Ghose[†] Aditya Agrawal[¶] Niladrish Chatterjee[¶] Abhijith Kashyap[†] Donghyuk Lee[¶] Mike O'Connor^{¶,‡} Hasan Hassan[§] Onur Mutlu^{§,†}

[†]Carnegie Mellon University [¶]NVIDIA [‡]The University of Texas at Austin [§]ETH Zürich

High DRAM Power Consumption

Problem: High DRAM (memory) power in today's systems





>40% in POWER7 (Ware+, HPCA'10)

>40% in GPU (Paul+, ISCA'15)

Low-Voltage Memory

- Existing DRAM designs to help reduce DRAM power by lowering supply voltage conservatively
 - Power $\propto Voltage^2$
- DDR3L (low-voltage) reduces voltage from 1.5V to 1.35V (-10%)
- LPDDR4 (low-power) employs low-power I/O interface with I.2V (lower bandwidth)

Can we reduce DRAM power and energy by further reducing supply voltage?

Goals

Understand and characterize the various characteristics of DRAM under reduced voltage

2 Develop a mechanism that reduces DRAM energy by lowering voltage while keeping performance loss within a target

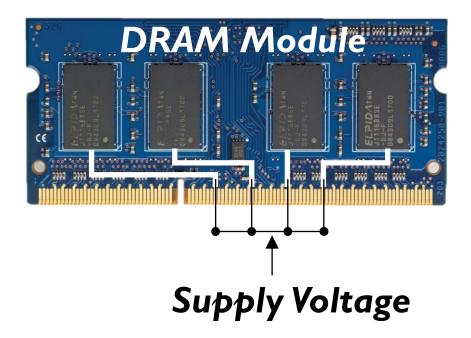
Key Questions

 How does reducing voltage affect reliability (errors)?

 How does reducing voltage affect DRAM latency?

 How do we design a new DRAM energy reduction mechanism?

Supply Voltage Control on DRAM



Adjust the supply voltage to every chip on the same module

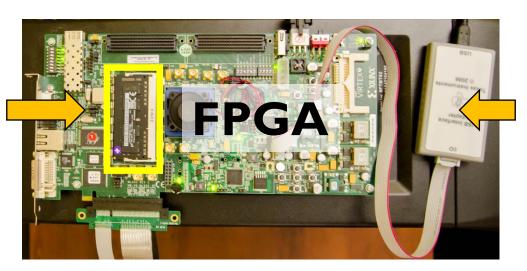
Custom Testing Platform

SoftMC [Hassan+, HPCA'17]: FPGA testing platform to

- I) Adjust supply voltage to DRAM modules
- 2) Schedule DRAM commands to DRAM modules

Existing systems: DRAM commands not exposed to users

DRAM module



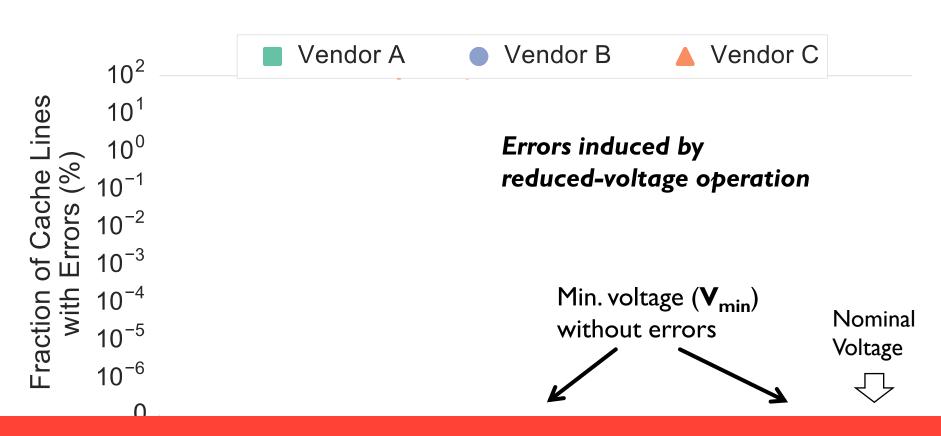
Voltage controller

https://github.com/CMU-SAFARI/DRAM-Voltage-Study

Tested DRAM Modules

- I24 DDR3L (low-voltage) DRAM chips
 - 31 SO-DIMMs
 - I.35V (DDR3 uses I.5V)
 - Density: 4Gb per chip
 - Three major vendors/manufacturers
 - Manufacturing dates: 2014-2016
- Iteratively read every bit in each 4Gb chip under a wide range of supply voltage levels: I.35V to I.0V (-26%)

Reliability Worsens with Lower Voltage

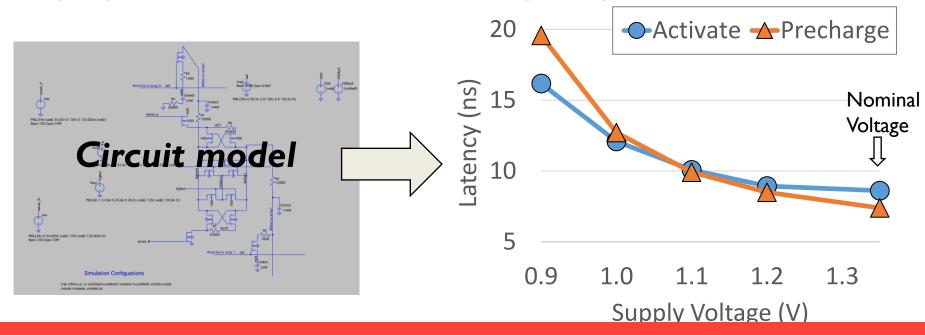


Reducing voltage below V_{min} causes an increasing number of errors

Source of Errors

Detailed circuit simulations (SPICE) of a DRAM cell array to model the behavior of DRAM operations

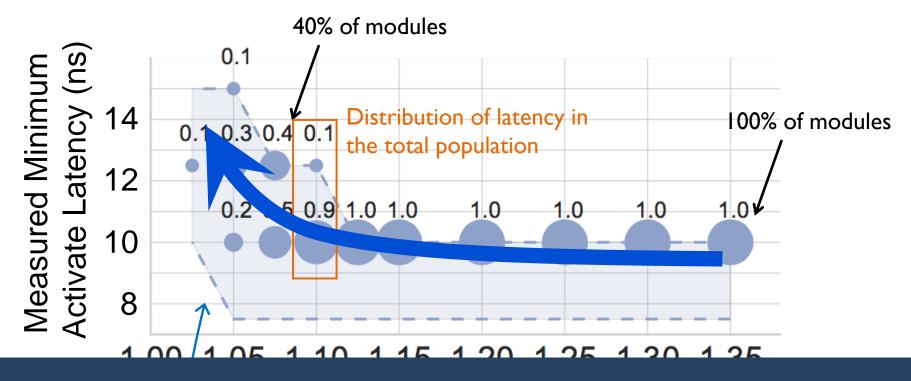
https://github.com/CMU-SAFARI/DRAM-Voltage-Study



Reliable low-voltage operation requires higher latency

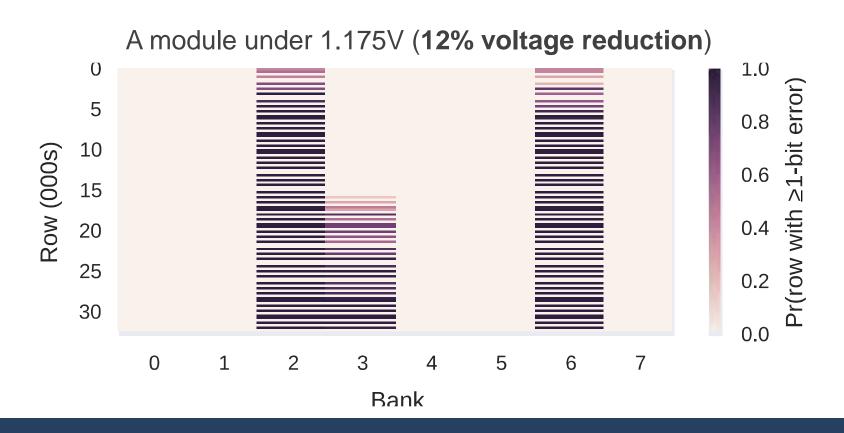
DIMMs Operating at Higher Latency

Measured minimum latency that does not cause errors in DRAM modules



DRAM requires longer latency to access data without errors at lower voltage

Spatial Locality of Errors



Errors concentrate in certain regions

Summary of Key Experimental Observations

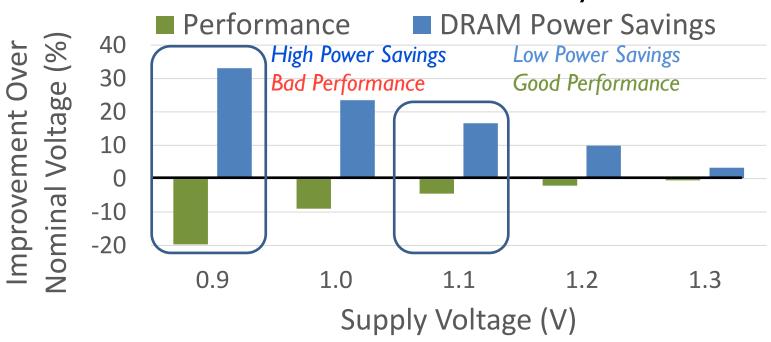
• Voltage-induced errors increase as voltage reduces further below V_{min}

Errors exhibit spatial locality

 Increasing the latency of DRAM operations mitigates voltage-induced errors

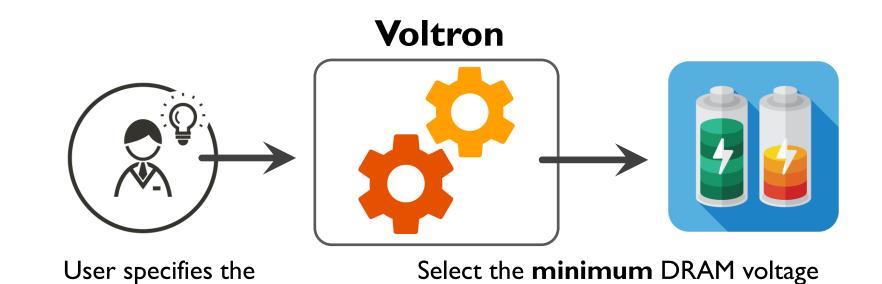
DRAM Voltage Adjustment to Reduce Energy

- Goal: Exploit the trade-off between voltage and latency to reduce energy consumption
- Approach: Reduce DRAM voltage reliably
 - Performance loss due to increased latency at lower voltage



Voltron Overview

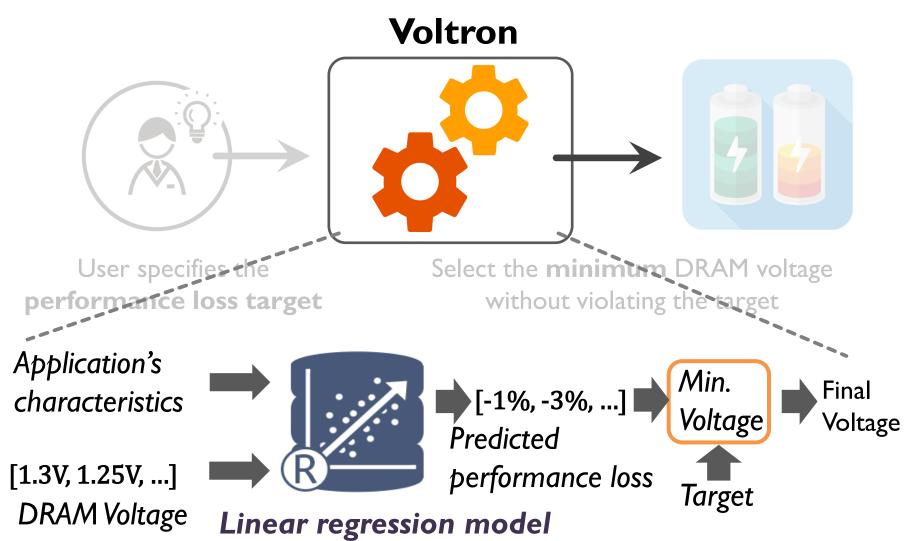
performance loss target



How do we predict performance loss due to increased latency under low DRAM voltage?

without violating the target

Linear Model to Predict Performance



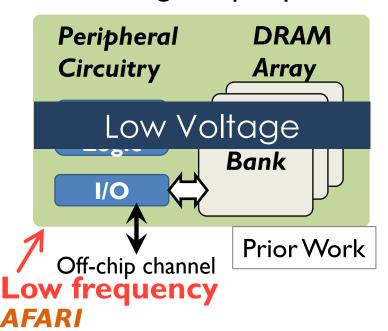
Regression Model to Predict Performance

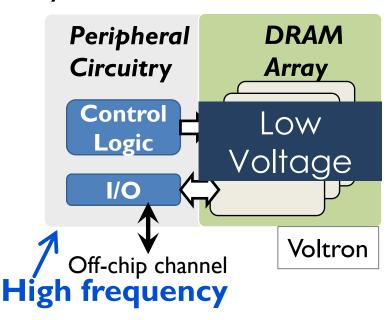
- Application's characteristics for the model:
 - Memory intensity: Frequency of last-level cache misses
 - Memory stall time: Amount of time memory requests stall commit inside CPU

- Handling multiple applications:
 - Predict a performance loss for each application
 - Select the minimum voltage that satisfies the performance target for all applications

Comparison to Prior Work

- <u>Prior work</u>: Dynamically scale *frequency and voltage* of the entire DRAM based on bandwidth demand [David+, ICAC'11]
 - Problem: Lowering voltage on the peripheral circuitry decreases channel frequency (memory data throughput)
- <u>Voltron</u>: Reduce voltage to only <u>DRAM array</u> without changing the voltage to peripheral circuitry

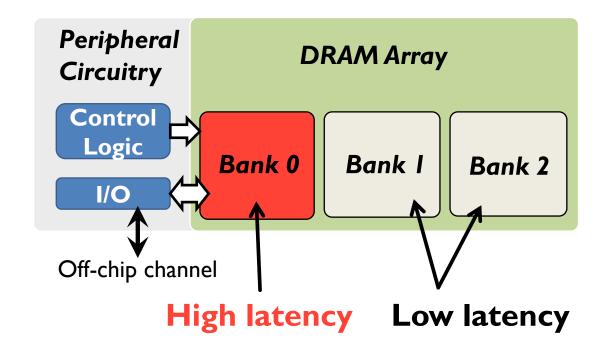




Exploiting Spatial Locality of Errors

Key idea: Increase the latency only for DRAM banks that observe errors under low voltage

Benefit: Higher performance



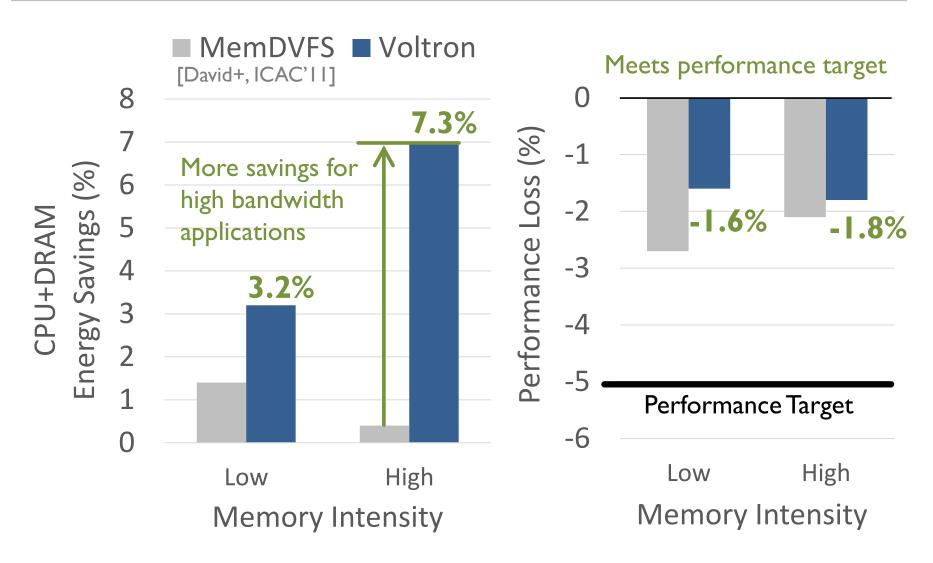
Voltron Evaluation Methodology

- Cycle-level simulator: Ramulator [CAL'15]
 - McPAT and DRAMPower for energy measurement

https://github.com/CMU-SAFARI/ramulator

- **4-core** system with DDR3L memory
- Benchmarks: SPEC2006, YCSB
- Comparison to prior work: MemDVFS [David+, ICAC'11]
 - Dynamic DRAM frequency and voltage scaling
 - Scaling based on the memory bandwidth consumption

Energy Savings with Bounded Performance





Voltron: Advantages & Disadvantages

Advantages

- + Can trade-off between voltage and latency to improve energy or performance
 - + Can exploit the high voltage margin present in DRAM

Disadvantages

 Requires finding the reliable operating voltage for each chip → higher testing cost

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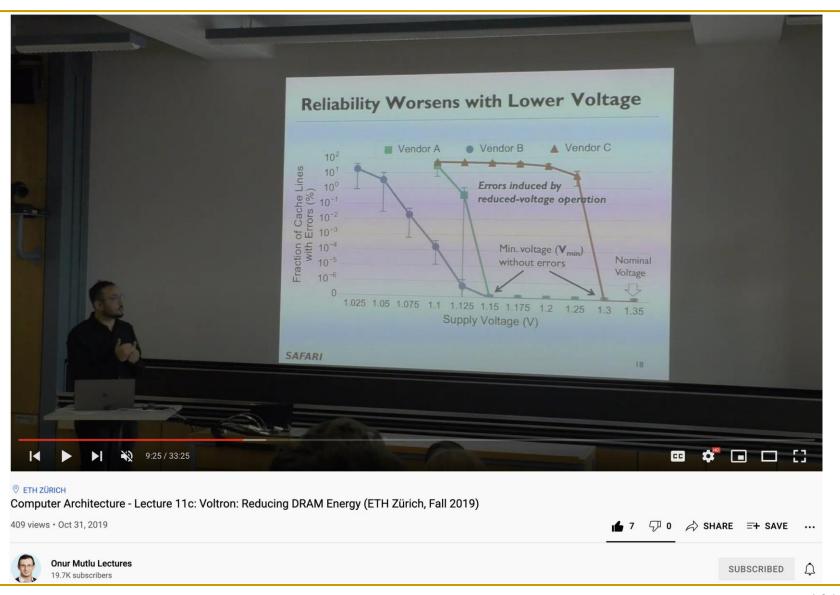
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[†]Carnegie Mellon University [¶]NVIDIA [‡]The University of Texas at Austin [§]ETH Zürich

More on Voltron



Reducing Memory Latency to Support Security Primitives

Using Memory for Security

- Generating True Random Numbers (using DRAM)
 - Kim et al., HPCA 2019
 - Olgun et al., ISCA 2021

- Evaluating Physically Unclonable Functions (using DRAM)
 - □ Kim et al., HPCA 2018

- Quickly Destroying In-Memory Data (using DRAM)
 - Orosa et al., arxiv 2019 + ISCA 2021

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

<u>Jeremie S. Kim</u> Minesh Patel Hasan Hassan Lois Orosa Onur Mutlu

SAFARI

HPCA 2019



Carnegie Mellon

D-RaNGe Executive Summary

- Motivation: High-throughput true random numbers enable system security and various randomized algorithms.
 - Many systems (e.g., IoT, mobile, embedded) do not have dedicated True
 Random Number Generator (TRNG) hardware but have DRAM devices
- **Problem**: Current DRAM-based TRNGs either
 - 1. do **not** sample a fundamentally non-deterministic entropy source
 - 2. are **too slow** for continuous high-throughput operation
- <u>Goal</u>: A novel and effective TRNG that uses <u>existing</u> commodity DRAM to provide random values with 1) <u>high-throughput</u>, 2) <u>low latency</u> and 3) no adverse effect on concurrently running applications
- <u>D-RaNGe:</u> Reduce DRAM access latency **below reliable values** and exploit DRAM cells' failure probabilities to generate random values
- Evaluation:
 - 1. Experimentally characterize 282 real LPDDR4 DRAM devices
 - 2. **D-RaNGe** (717.4 Mb/s) has significantly higher throughput (211x)
 - 3. **D-RaNGe (100ns)** has significantly lower latency (180x)

SAFARI

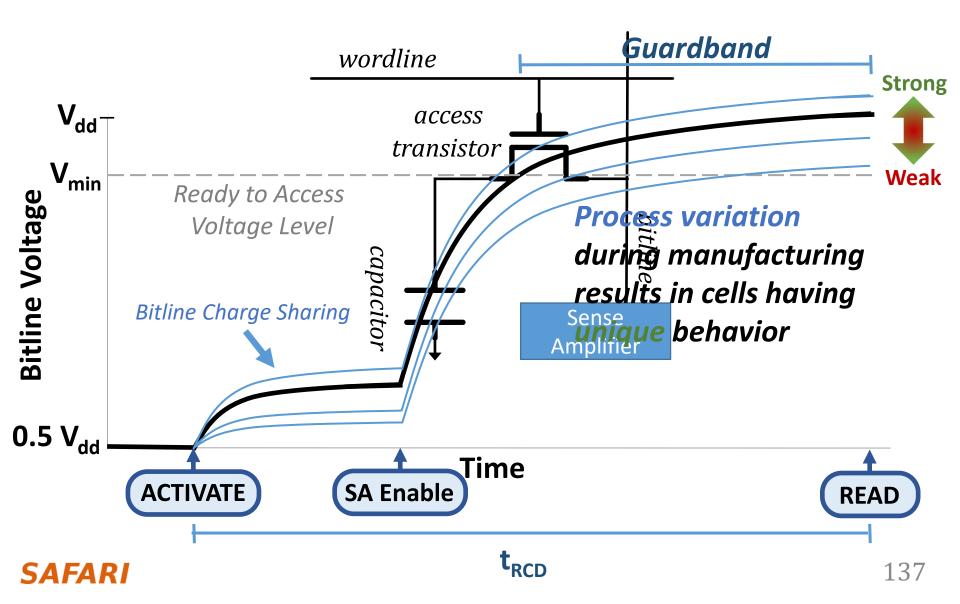
DRAM Latency Characterization of 282 LPDDR4 DRAM Devices

 Latency failures come from accessing DRAM with reduced timing parameters.

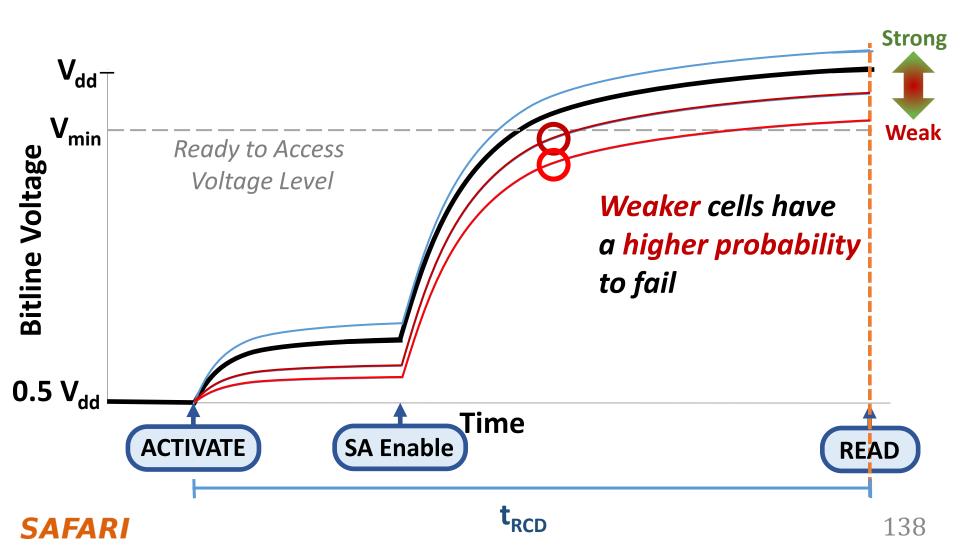
Key Observations:

- 1. A cell's **latency failure** probability is determined by **random process variation**
- 2. Some cells fail randomly

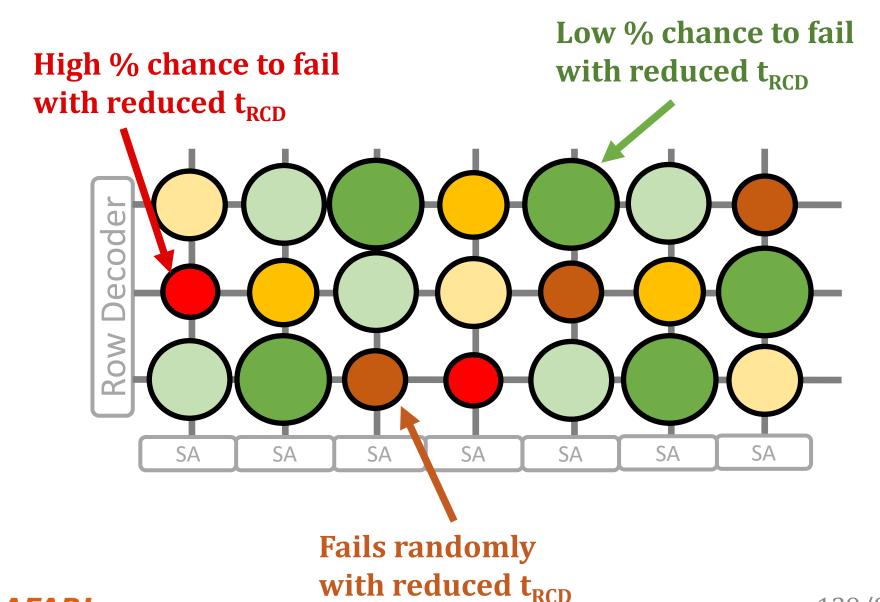
DRAM Accesses and Failures



DRAM Accesses and Failures



D-RaNGe Key Idea





D-RaNGe Key Idea

High % chance to fail with reduced t_{RCD}

Low % chance to fail with reduced t_{RCD}

We refer to cells that fail randomly when accessed with a reduced t_{RCD} as RNG cells



Fails randomly with reduced t_{RCD}

Our D-RaNGe Evaluation

- We generate random values by repeatedly accessing RNG cells and aggregating the data read
- The random data satisfies the NIST statistical test suite for randomness
- The D-RaNGE generates random numbers
 - **Throughput**: 717.4 Mb/s
 - **Latency**: 64 bits in <1us
 - Power: 4.4 nJ/bit

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

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SAFARI

HPCA 2019



Carnegie Mellon

More on D-RaNGe

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[Slides (pptx) (pdf)]

[Full Talk Video (21 minutes)]

[Full Talk Lecture Video (27 minutes)]

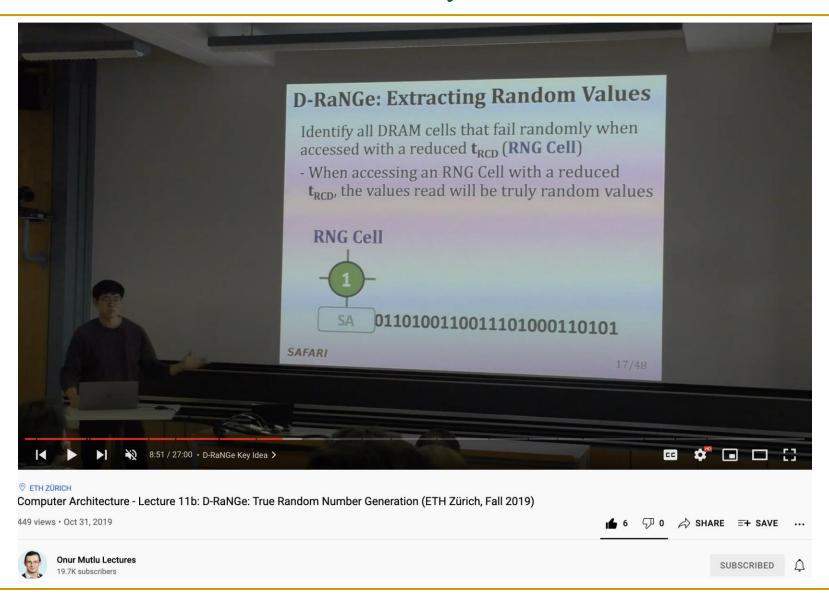
Top Picks Honorable Mention by IEEE Micro.

D-RaNGe: Using Commodity DRAM Devices to Generate True Random Numbers with Low Latency and High Throughput

Jeremie S. Kim^{‡§} Minesh Patel[§] Hasan Hassan[§] Lois Orosa[§] Onur Mutlu^{§‡} [‡]Carnegie Mellon University [§]ETH Zürich

SAFARI 143

More on DRAM Latency TRNGs



Doing Better Than D-RaNGe

 Ataberk Olgun, Minesh Patel, A. Giray Yaglikci, Haocong Luo, Jeremie S. Kim, F. Nisa Bostanci, Nandita Vijaykumar, Oguz Ergin, and Onur Mutlu,

"QUAC-TRNG: High-Throughput True Random Number Generation Using Quadruple Row Activation in Commodity DRAM Chips"

Proceedings of the <u>48th International Symposium on Computer Architecture</u> (**ISCA**), Virtual, June 2021.

[Slides (pptx) (pdf)]

[Short Talk Slides (pptx) (pdf)]

[Talk Video (25 minutes)]

[SAFARI Live Seminar Video (1 hr 26 mins)]

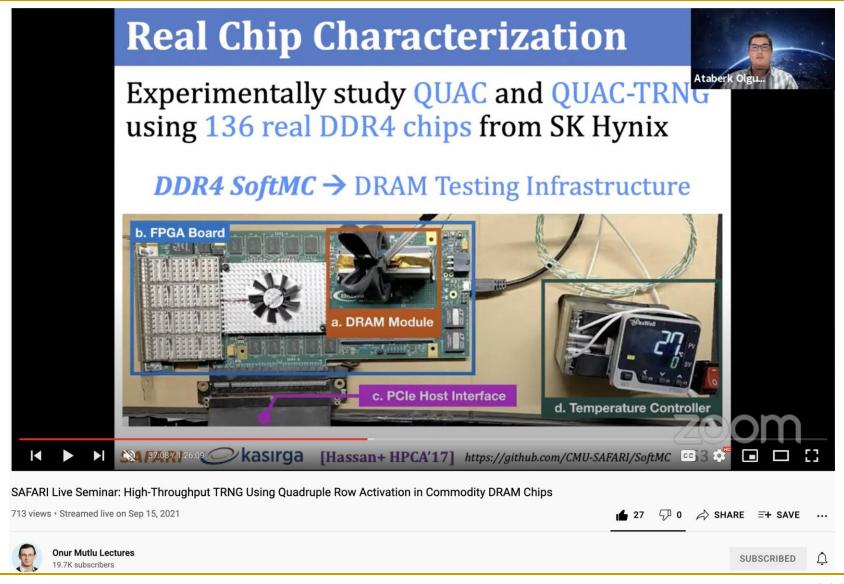
QUAC-TRNG: High-Throughput True Random Number Generation Using Quadruple Row Activation in Commodity DRAM Chips

Ataberk Olgun^{§†} Minesh Patel[§] A. Giray Yağlıkçı[§] Haocong Luo[§] Jeremie S. Kim[§] F. Nisa Bostancı^{§†} Nandita Vijaykumar^{§⊙} Oğuz Ergin[†] Onur Mutlu[§]

§ETH Zürich † TOBB University of Economics and Technology $^{\odot}$ University of Toronto

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More on QUAC-TRNG



DRAM Latency PUFs

Jeremie S. Kim, Minesh Patel, Hasan Hassan, and Onur Mutlu,
 "The DRAM Latency PUF: Quickly Evaluating Physical Unclonable
 Functions by Exploiting the Latency-Reliability Tradeoff in Modern DRAM Devices"

Proceedings of the <u>24th International Symposium on High-Performance Computer</u> <u>Architecture</u> (**HPCA**), Vienna, Austria, February 2018.

[Lightning Talk Video]

[Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)]

[Full Talk Lecture Video (28 minutes)]

The DRAM Latency PUF:

Quickly Evaluating Physical Unclonable Functions by Exploiting the Latency-Reliability Tradeoff in Modern Commodity DRAM Devices

Jeremie S. Kim^{†§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§†}

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The DRAM Latency PUF:

Quickly Evaluating Physical Unclonable Functions by Exploiting the Latency-Reliability Tradeoff in Modern Commodity DRAM Devices

> <u>Jeremie S. Kim</u> Minesh Patel Hasan Hassan Onur Mutlu







Carnegie Mellon

DL-PUF: Executive Summary

Motivation:

- We can authenticate a system via unique signatures if we can evaluate a Physical Unclonable Function (PUF) on it
- Signatures (PUF response) reflect inherent properties of a device
- DRAM is a promising substrate for PUFs because it is widely used
- **Problem**: Current DRAM PUFs are 1) very slow, 2) require a DRAM reboot, or 3) require additional custom hardware
- <u>Goal</u>: To develop a novel and effective PUF for <u>existing</u> commodity DRAM devices with <u>low-latency evaluation time</u> and <u>low system interference</u> across <u>all operating temperatures</u>
- <u>DRAM Latency PUF:</u> Reduce DRAM access latency below reliable values and exploit the resulting error patterns as unique identifiers

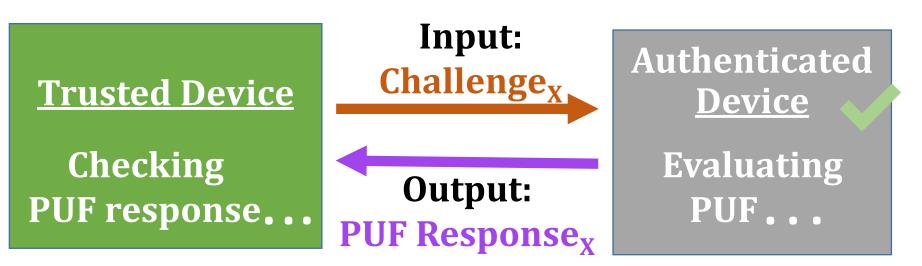
• Evaluation:

- 1. Experimentally characterize **223 real LPDDR4 DRAM devices**
- 2. **DRAM latency PUF** (88.2 ms) achieves a speedup of **102x/860x** at 70°C/55°C over prior DRAM PUF evaluation mechanisms

Motivation

We want a way to ensure that a system's components are not **compromised**

- Physical Unclonable Function (PUF): a function we evaluate on a device to generate a signature unique to the device
- We refer to the unique signature as a PUF response
- Often used in a Challenge-Response Protocol (CRP)



150/4

Motivation

- 1. We want a runtime-accessible PUF
 - Should be evaluated **quickly** with **minimal** impact on concurrent applications
 - Can protect against attacks that swap system components with malicious parts

- **2.** DRAM is a **promising substrate** for evaluating PUFs because it is **ubiquitous** in modern systems
 - Unfortunately, current DRAM PUFs are slow and get exponentially slower at lower temperatures

DRAM Latency Characterization of 223 LPDDR4 DRAM Devices

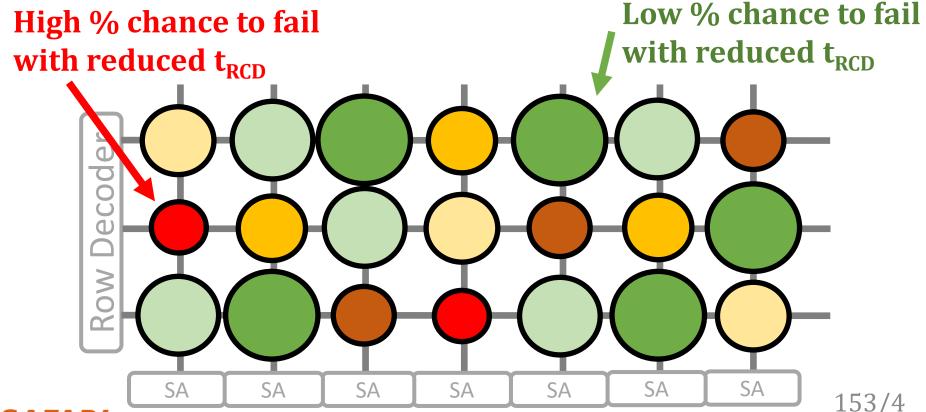
 Latency failures come from accessing DRAM with reduced timing parameters.

Key Observations:

- 1. A cell's **latency failure** probability is determined by **random process variation**
- 2. Latency failure patterns are repeatable and unique to a device

DRAM Latency PUF Key Idea

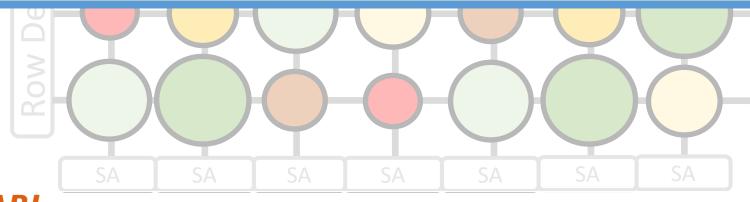
- A cell's latency failure probability is inherently related to random process variation from manufacturing
- We can provide repeatable and unique device signatures using latency error patterns



DRAM Latency PUF Key Idea

- A cell's latency failure probability is inherently related to random process variation from manufacturing
- We can provide repeatable and unique device

The key idea is to compose a PUF response using the DRAM cells that fail with high probability



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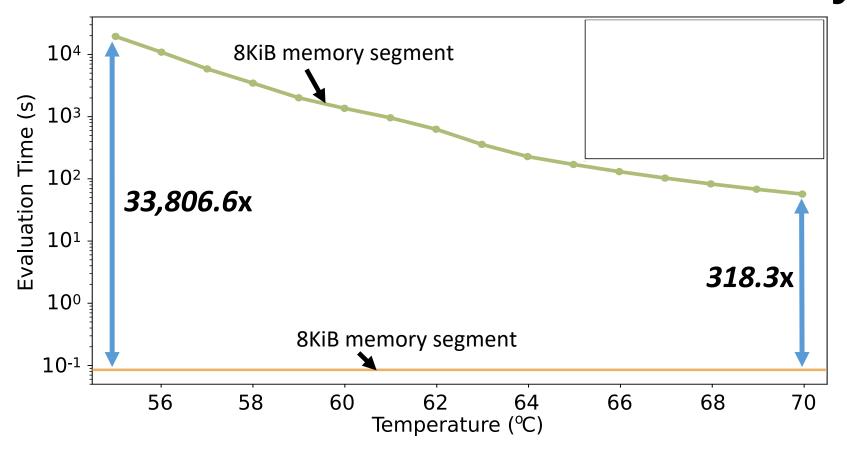
The DRAM Latency PUF Evaluation

 We generate PUF responses using latency errors in a region of DRAM

The latency error patterns satisfy PUF requirements

 The DRAM Latency PUF generates PUF responses in 88.2ms

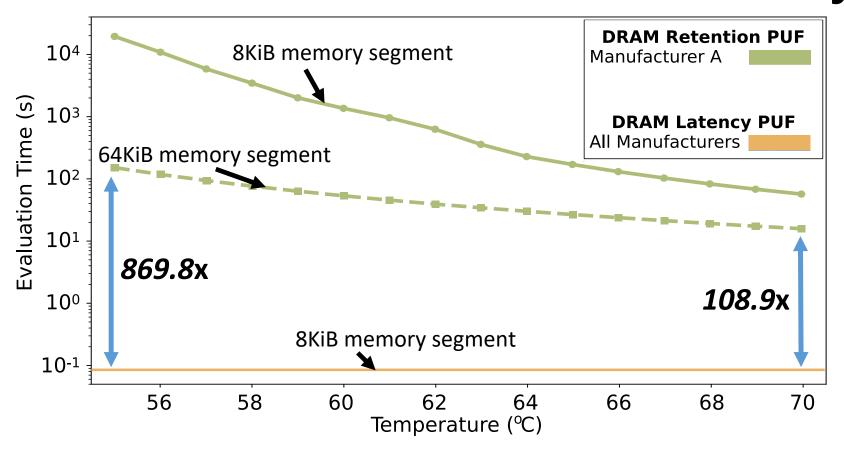
Results – PUF Evaluation Latency



DRAM latency PUF is

1. Fast and constant latency (88.2ms)

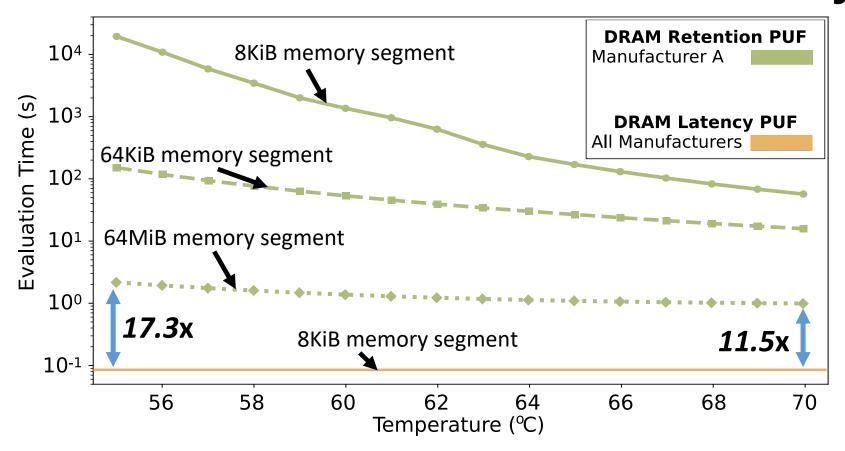
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DRAM latency PUF is

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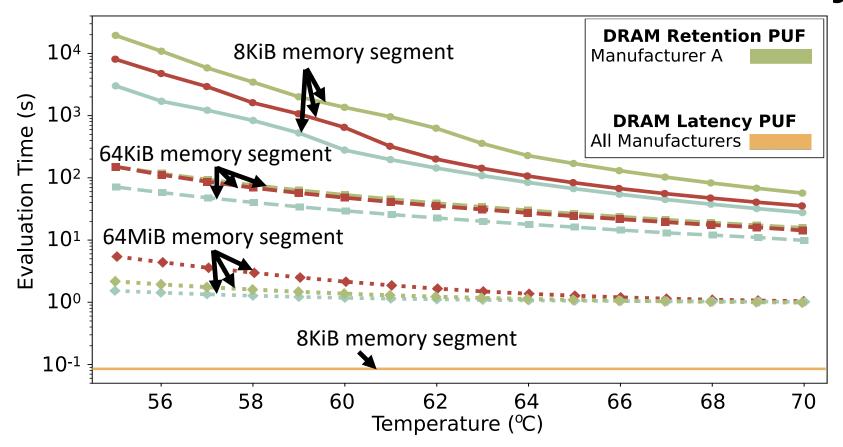
Results – PUF Evaluation Latency



DRAM latency PUF is

1. Fast and constant latency (88.2ms)

Results – PUF Evaluation Latency



DRAM latency PUF is

- 1. Fast and constant latency (88.2ms)
- 2. On average, 102x/860x faster than the previous DRAM PUF with the same DRAM capacity overhead (64KiB)

159/4

Other Results in the Paper

- How the DRAM latency PUF meets the basic requirements for an effective PUF
- A detailed analysis on:
 - Devices of the three major DRAM manufacturers
 - The evaluation time of a PUF

Further discussion on:

- **Optimizing** retention PUFs
- **System interference** of DRAM retention and latency PUFs
- Algorithm to quickly and reliably evaluate DRAM latency PUF
- **Design considerations** for a DRAM latency PUF
- The DRAM Latency PUF overhead analysis

The DRAM Latency PUF:

Quickly Evaluating Physical Unclonable Functions by Exploiting the Latency-Reliability Tradeoff in Modern Commodity DRAM Devices

<u>Jeremie S. Kim</u> Minesh Patel Hasan Hassan Onur Mutlu



HPCA 2018



QR Code for the paper

https://people.inf.ethz.ch/omutlu/pub/dram-latency-puf hpca18.pdf





Carnegie Mellon

More on DRAM Latency PUFs

Jeremie S. Kim, Minesh Patel, Hasan Hassan, and Onur Mutlu,
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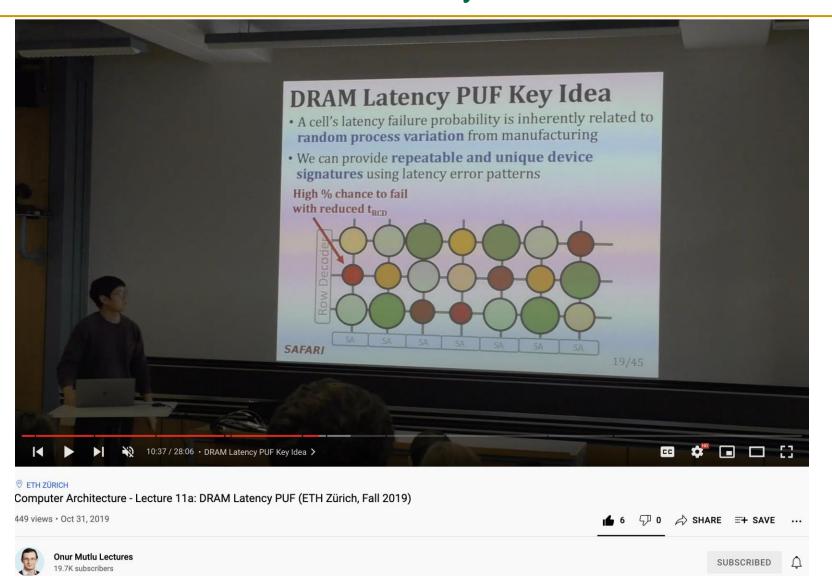
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Jeremie S. Kim^{†§} Minesh Patel[§] Hasan Hassan[§] Onur Mutlu^{§†}

[†]Carnegie Mellon University [§]ETH Zürich

More on DRAM Latency PUFs



Reducing Memory Latency by Exploiting Memory Access Patterns

ChargeCache: Executive Summary

 <u>Goal</u>: Reduce average DRAM access latency with no modification to the existing DRAM chips

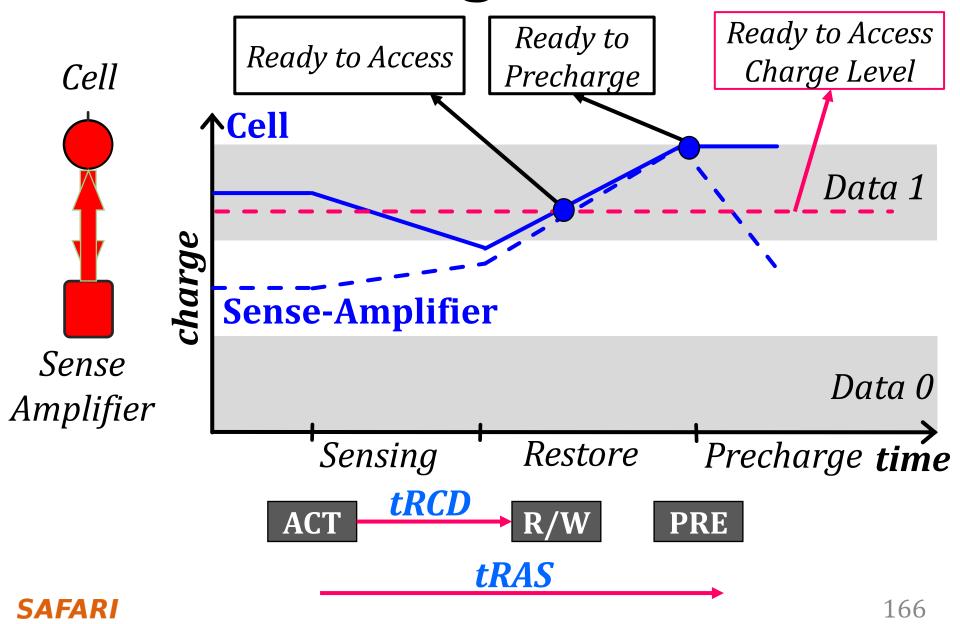
• Observations:

- 1) A highly-charged DRAM row can be accessed with low latency
- 2) A row's charge is restored when the row is accessed
- 3) A recently-accessed row is likely to be accessed again: Row Level Temporal Locality (RLTL)
- <u>Key Idea</u>: Track recently-accessed DRAM rows and use lower timing parameters if such rows are accessed again

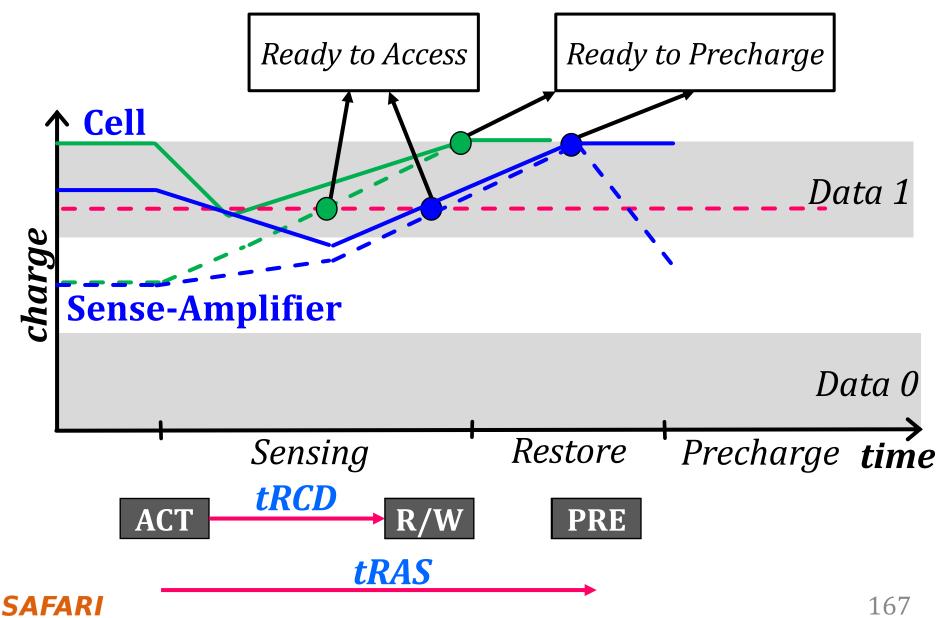
ChargeCache:

- Low cost & no modifications to the DRAM
- Higher performance (8.6-10.6% on average for 8-core)
- Lower DRAM energy (7.9% on average)

DRAM Charge over Time



Accessing Highly-charged Rows



Observation 1

A highly-charged DRAM row can be accessed with low latency

• tRCD: 44%



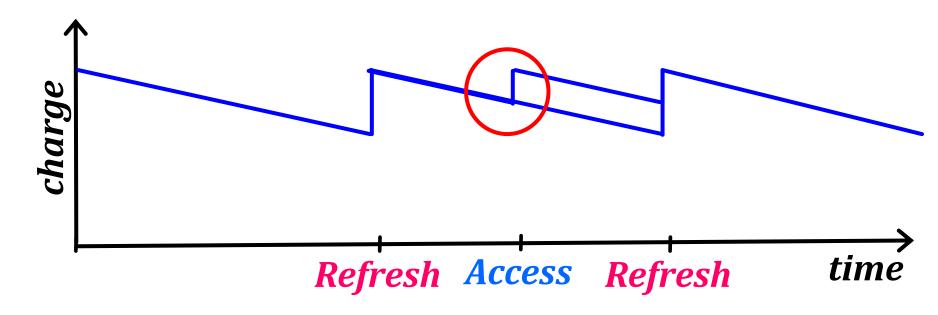
• tRAS: **37%**

How does a row become highly-charged?

How Does a Row Become Highly-Charged?

DRAM cells **lose charge** over time Two ways of restoring a row's charge:

- Refresh Operation
- Access



Observation 2

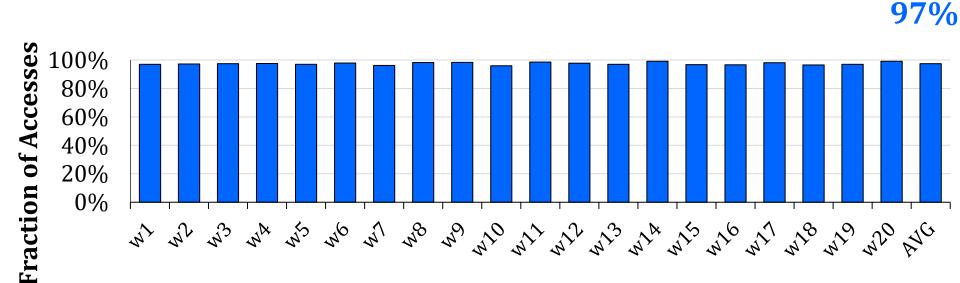
A row's charge is restored when the row is accessed

How likely is a recently-accessed row to be accessed again?

Row Level Temporal Locality (RLTL)

A recently-accessed DRAM row is likely to be accessed again.

• *t*-RLTL: Fraction of rows that are accessed within time *t* after their previous access



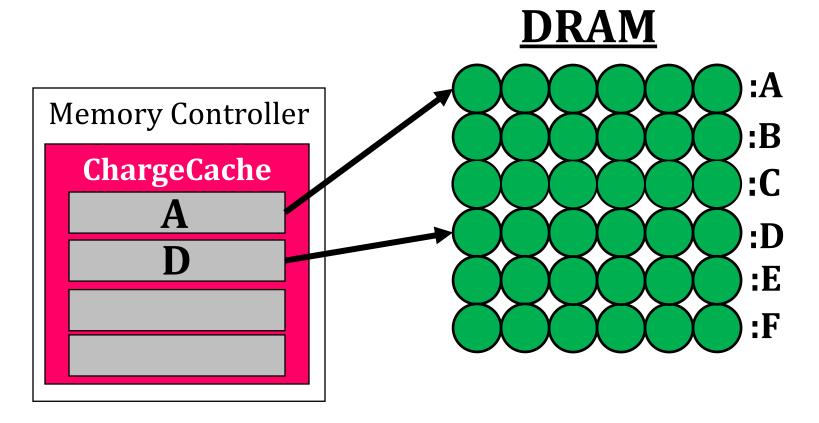
88mss - RITLIftorseight-core workloads



Key Idea

Track recently-accessed DRAM rows and use lower timing parameters if such rows are accessed again

ChargeCache Overview



Requests: A D A

Change Gabbe Whits: When Defautt Timings

Area and Power Overhead

Modeled with CACTI

Area

- − ~5KB for 128-entry ChargeCache
- 0.24% of a 4MB Last Level Cache (LLC) area

Power Consumption

- 0.15 mW on average (static + dynamic)
- 0.23% of the 4MB LLC power consumption

SAFARI

Methodology

Simulator

DRAM Simulator (Ramulator [Kim+, CAL'15])
 https://github.com/CMU-SAFARI/ramulator

Workloads

- 22 single-core workloads
 - SPEC CPU2006, TPC, STREAM
- 20 multi-programmed 8-core workloads
 - By randomly choosing from single-core workloads
- Execute at least 1 billion representative instructions per core (Pinpoints)

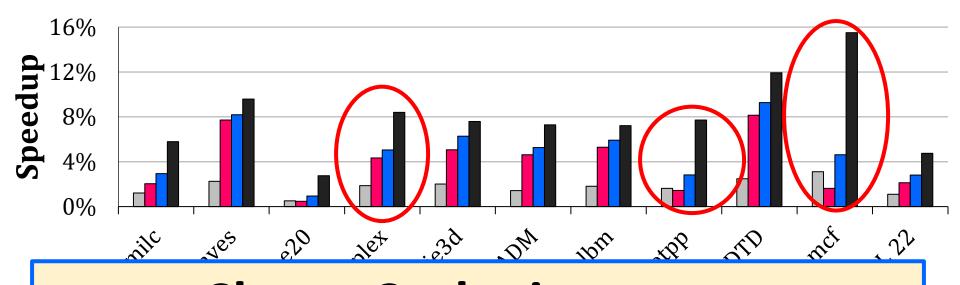
System Parameters

- 1/8 core system with 4MB LLC
- Default tRCD/tRAS of 11/28 cycles

Single-core Performance







ChargeCache improves single-core performance

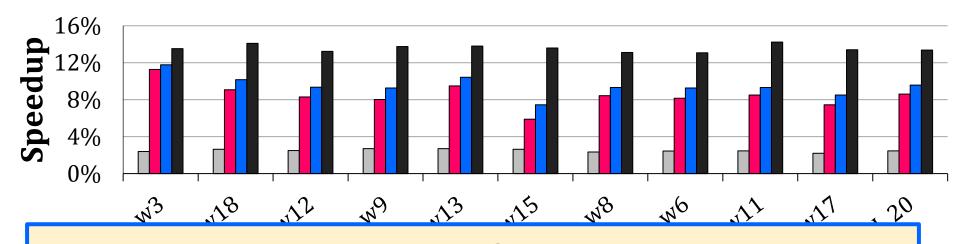
Eight-core Performance

NUAT 2.5%

ChargeCache 9%

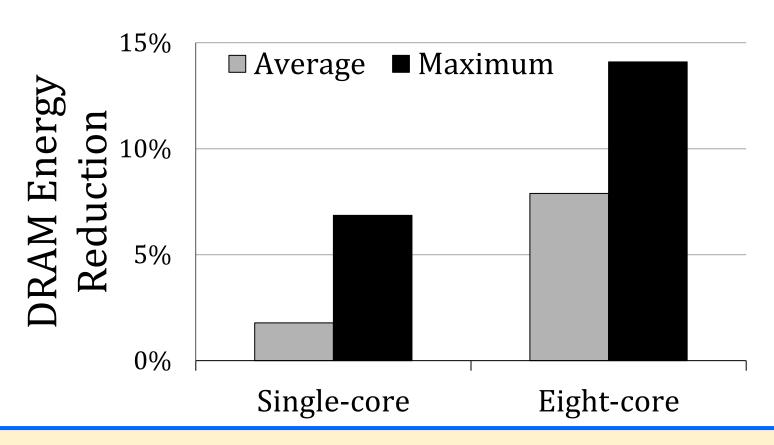
ChargeCache + NUAT

LL-DRAM (Upperbound) 13%



ChargeCache significantly improves multi-core performance

DRAM Energy Savings



ChargeCache reduces DRAM energy

More on ChargeCache

 Hasan Hassan, Gennady Pekhimenko, Nandita Vijaykumar, Vivek Seshadri, Donghyuk Lee, Oguz Ergin, and Onur Mutlu,
 "ChargeCache: Reducing DRAM Latency by Exploiting Row Access Locality"

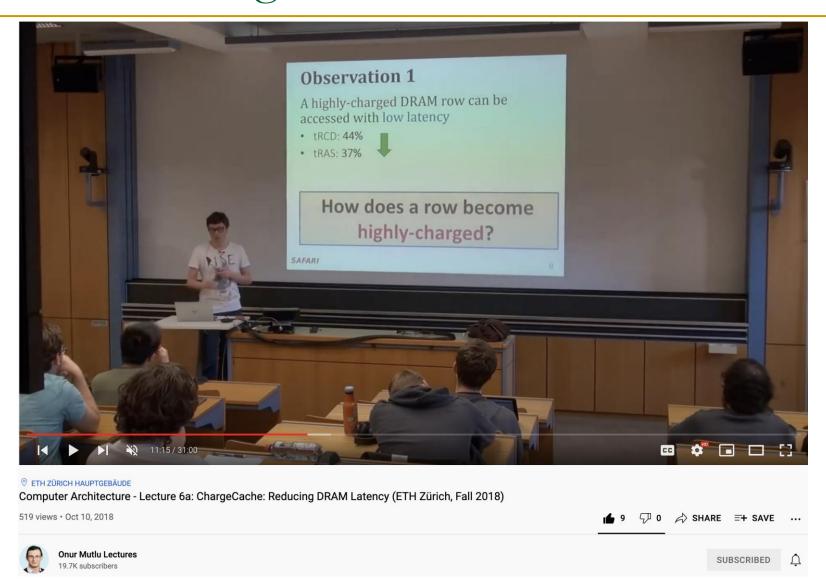
Proceedings of the <u>22nd International Symposium on High-</u> <u>Performance Computer Architecture</u> (**HPCA**), Barcelona, Spain, March 2016.

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[Source Code]

ChargeCache: Reducing DRAM Latency by Exploiting Row Access Locality

Hasan Hassan^{†*}, Gennady Pekhimenko[†], Nandita Vijaykumar[†] Vivek Seshadri[†], Donghyuk Lee[†], Oguz Ergin^{*}, Onur Mutlu[†]

More on ChargeCache



Partial Restoration of Cell Charge

 Yaohua Wang, Arash Tavakkol, Lois Orosa, Saugata Ghose, Nika Mansouri Ghiasi, Minesh Patel, Jeremie S. Kim, Hasan Hassan, Mohammad Sadrosadati, and Onur Mutlu,

"Reducing DRAM Latency via Charge-Level-Aware Look-Ahead Partial Restoration"

Proceedings of the <u>51st International Symposium on</u> <u>Microarchitecture</u> (**MICRO**), Fukuoka, Japan, October 2018.

Reducing DRAM Latency via Charge-Level-Aware Look-Ahead Partial Restoration

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Yaohua Wang<sup>†§</sup> Arash Tavakkol<sup>†</sup> Lois Orosa<sup>†*</sup> Saugata Ghose<sup>‡</sup> Nika Mansouri Ghiasi<sup>†</sup> Minesh Patel<sup>†</sup> Jeremie S. Kim<sup>‡†</sup> Hasan Hassan<sup>†</sup> Mohammad Sadrosadati<sup>†</sup> Onur Mutlu<sup>†‡</sup> 

<sup>†</sup>ETH Zürich <sup>§</sup>National University of Defense Technology <sup>‡</sup>Carnegie Mellon University *University of Campinas
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On DRAM Power Consumption

VAMPIRE DRAM Power Model

Saugata Ghose, A. Giray Yaglikci, Raghav Gupta, Donghyuk Lee, Kais Kudrolli, William X. Liu, Hasan Hassan, Kevin K. Chang, Niladrish Chatterjee, Aditya Agrawal, Mike O'Connor, and Onur Mutlu,

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[Abstract]

[POMACS Journal Version (same content, different format)]

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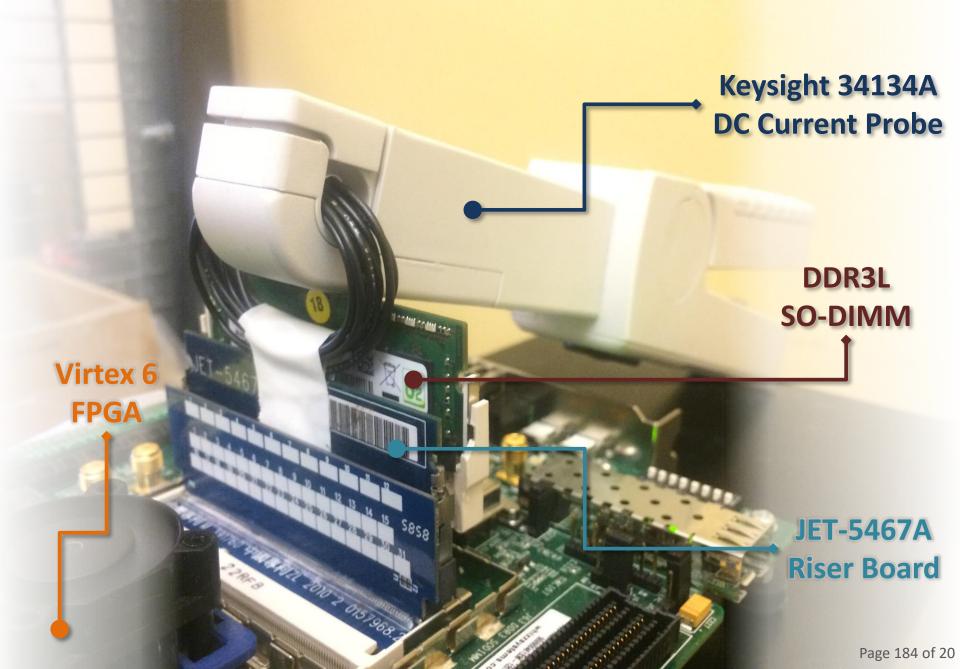
[VAMPIRE DRAM Power Model]

What Your DRAM Power Models Are Not Telling You: Lessons from a Detailed Experimental Study

Saugata Ghose[†] Abdullah Giray Yağlıkçı^{‡†} Raghav Gupta[†] Donghyuk Lee[§] Kais Kudrolli[†] William X. Liu[†] Hasan Hassan[‡] Kevin K. Chang[†] Mike O'Connor[§]¶ Onur Mutlu^{‡†} Niladrish Chatterjee[§] Aditya Agrawal[§]

Power Measurement Platform



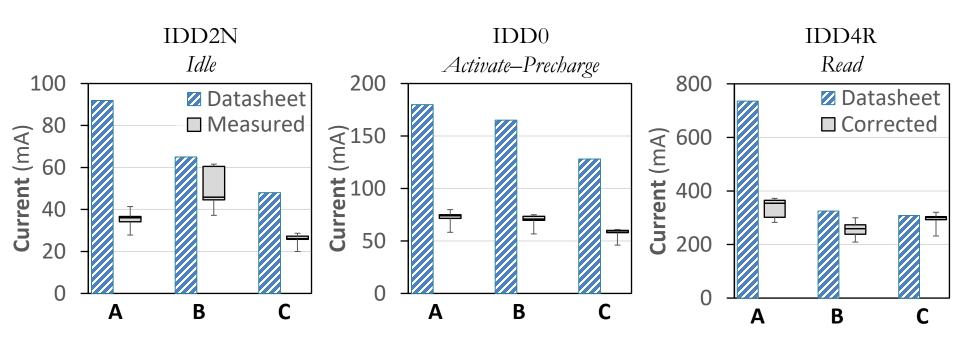


Power Measurement Methodology



- SoftMC: an FPGA-based memory controller [Hassan+ HPCA '17]
 - Modified to repeatedly loop commands
 - Open-source: https://github.com/CMU-SAFARI/SoftMC
- Measure current consumed by a module during a SoftMC test
- Tested 50 DDR3L DRAM modules (200 DRAM chips)
 - Supply voltage: 1.35 V
 - Three major vendors: A, B, C
 - Manufactured between 2014 and 2016
- For each experimental test that we perform
 - 10 runs of each test per module
 - At least 10 current samples per run

1. Real DRAM Power Varies Widely from IDD Values SAFARI

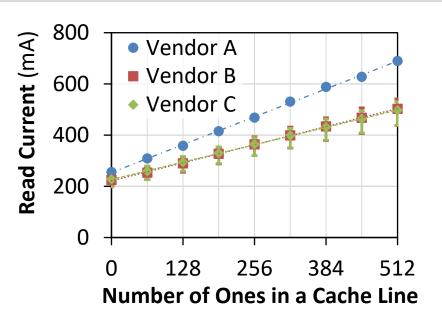


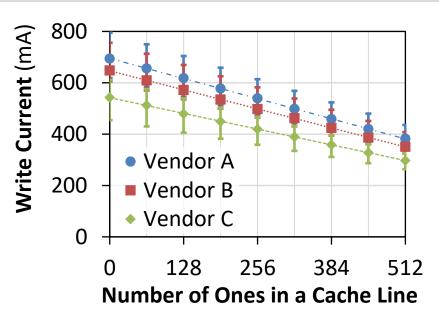
- Different vendors have very different margins (i.e., guardbands)
- Low variance among different modules from same vendor

Current consumed by real DRAM modules varies significantly for all IDD values that we measure

2. DRAM Power is Dependent on Data Values



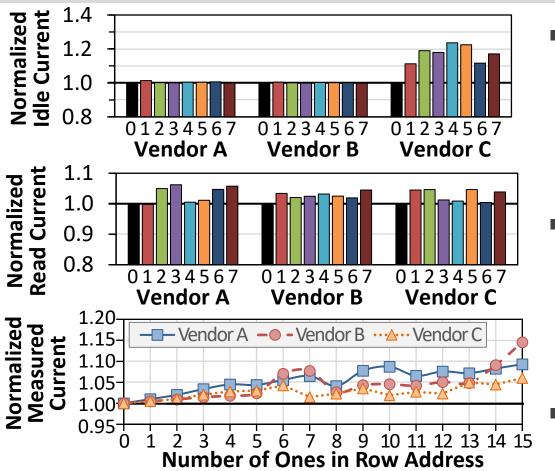




- Some variation due to infrastructure can be subtracted
- Without infrastructure variation: up to 230 mA of change
- Toggle affects power consumption, but < 0.15 mA per bit

DRAM power consumption depends *strongly* on the data value

3. Structural Variation Affects DRAM Power Usage SAFARI



Vendor C: variation in idle current across banks

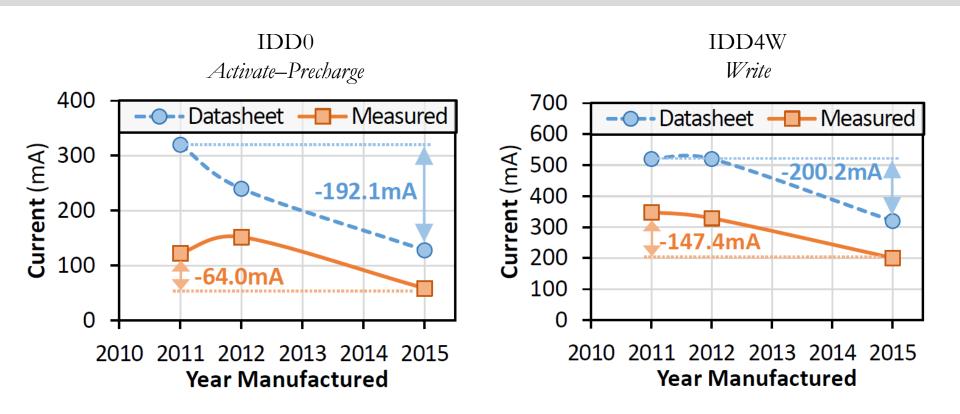
 All vendors: variation in read current across banks

• All vendors: variation in activation based on

Significant structural variation:

DRAM power varies systematically by bank and row

4. Generational Savings Are Smaller Than Expected SAFARI



Similar trends for idle and read currents

Actual power savings of newer DRAM is *much lower* than the savings indicated in the datasheets

- 1. Real DRAM modules often consume less power than vendor-provided IDD values state
- 2. DRAM power consumption is dependent on the data value that is read/written
- 3. Across banks and rows, structural variation affects power consumption of DRAM
- 4. Newer DRAM modules save less power than indicated in datasheets by vendors

Detailed observations and analyses in the paper

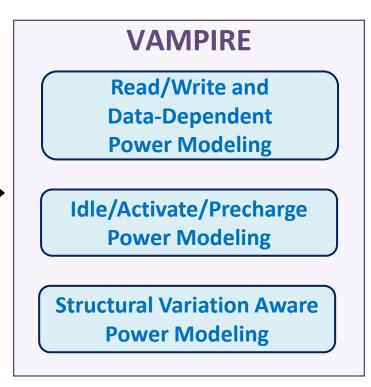
■ VAMPIRE: Variation-Aware model of Memory Power Informed by Real Experiments

Inputs

(from memory system simulator)

Trace of DRAM commands, timing

Data that is being written



Outputs

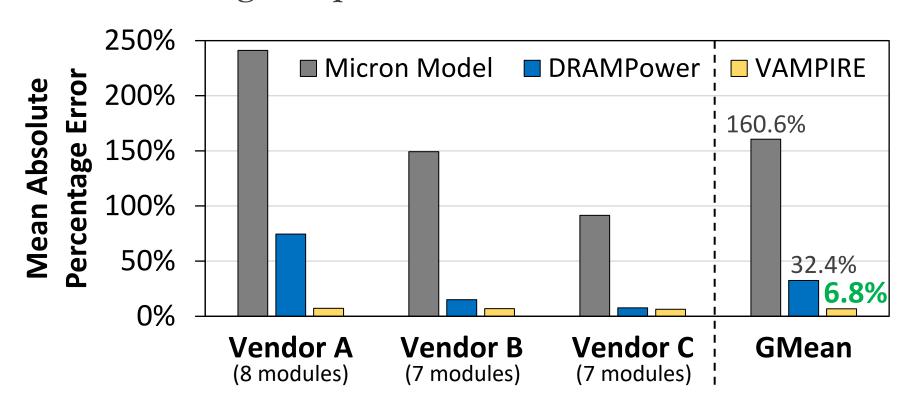
Per-vendor power consumption

Range for each vendor (optional)

■ VAMPIRE and raw characterization data are open-source: https://github.com/CMU-SAFARI/VAMPIRE

VAMPIRE Has Lower Error Than Existing Models SAFARI

Validated using new power measurements: details in the



VAMPIRE has very low error for all vendors: 6.8% Much more accurate than prior models

VAMPIRE Enables Several New Studies

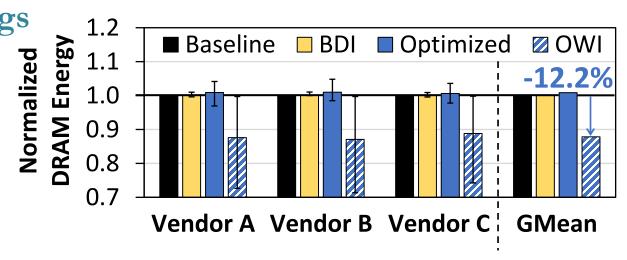


- Taking advantage of structural variation to perform variation-aware physical page allocation to reduce power
- Smarter DRAM power-down scheduling
- Reducing DRAM energy with data-dependency-aware

cache line encodings

• 23 applications from the SPEC 2006 benchmark suite

• Traces collected using Pin and Ramulator



■ We expect there to be many other new studies in the future

VAMPIRE DRAM Power Model

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